MYiR Make Your Idea Real

Product Brochure

A Global Provider of Embedded SOMs & Solutions

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MYiR Make Your Idea Real

Company Profile

MYIR Electronics Limited (MYIR for short), established in 2011, is a global provider of embedded System-On-Modules (SOMs) and comprehensive solutions based on various architectures such as ARM, FPGA, RISC-V, and AI. We cater to customers' needs for large-scale production, offering customized design, industry-specific application solutions, and one-stop OEM services.

MYIR, recognized as a national high-tech enterprise, is also listed among the "Specialized and Special new" Enterprises in Shenzhen, China. Our core belief is that "Our success stems from our customers' success" and embraces the philosophy of "Make Your Idea Real, then My Idea Realizing!"

ISO 14001 ISO 9001

15+ years Industry Expertise

45+ % R&D Personnel

7,000+ M² R&D and Manufacturing Base

150+ Patents & Honors

30,000+ Worldwide Customers

History

2011-2012

- Shenzhen Headquarter Established
- Beijing Office Established
- Shanghai Office Established
- Became ARM Approved Partner
- Became Xilinx Design Partner

2013-2017

- Became TI Design Network Partner
- Became NXP Approved Partner
- Became IDH Partner of AVNET
- Wuhan R&D Center Established
- Head Office Moved to Yunli Smart Park

2018-2021

- SMT Factory Established in Guanlan, Shenzhen
- Became ST Authorized Partner
- Became SemiDrive Design Partner
- Mouser Became Distributor
- Digi-key Became Distributor
- Qualified as National High-tech Enterprise
- ISO9001 certificated
- ISO14001 certificated

2022-2024

- Became IDH Partner of Renesas
- Became AllWinner Design Partner
- Awarded Quality Supplier of NARI Group
- Awarded Quality Supplier of XJ Group
- Honored with The Partner Award from ST
- Awarded with "Shenzhen Specialized and Special New Enterprise"

Main Business

- System-On-Modules (SOMs)
- Single Board Computers
- Solutions
- ODM Services
- OEM Services

Application Fields

- EV Charging Station
- Energy Storage
- Electric Power
- PLC
- Industrial Automation
- Industrial Gateway
- Commercial Display
- Medical Devices
- Engineering Machinery
- Rail Transport
- Industrial HMI
- AI Edge Computing

Corporate Culture

Mission

Laying the foundation for digital, intelligent, and networked embedded products to enable intelligent manufacturing and smart living.

Vision

To become the most trusted provider of embedded SOMs for industrial customers worldwide.

Values

Co-creation, win-win collaboration, and sharing, aiming to create maximum value for customers.

Information Management Platform

MYIR has developed a comprehensive range of professional and sophisticated enterprise-level information management platforms. These platforms enable comprehensive digital management across various dimensions, including material supply chain, product research and development, customer management, project management, employee management, production management, and more. Through these platforms, MYIR aims to achieve business digitization, management visualization, and intelligent production.

Enterprise Management
ERP System

Customer Management
CRM System

Supplier Management
SRM System

Product Management
PLM System, DFX System

Production Management
MES System, iDAS Electrostatic Monitoring System, WMS Intelligent Storage System

Business Philosophy

Leading Technology

Continuously engaging in technological innovation to provide customers with cutting-edge technologies and products.

Professional Service

Systematically establishing a customer service framework and offering comprehensive technical support throughout the entire sales cycle, from pre-sales to post-sales.

Delivery Commitment

Guaranteeing a product lifecycle of no less than 10 years.

Quality Assurance

The ISO management system runs through the entire process, from material selection to R&D, product testing, production, and shipment.

Qualifications and Honors

National High-Tech Enterprise

Shenzhen Specialized and Special New Enterprise


ISO9001


ISO14001

IDH Partner of Renesas


Partner Award from ST for MYIR

Quality Supplier of XJ Power Co., Ltd.

Quality Supplier of NARI Group

CE Certification

RoHS Certification


Software Copyright

Certificate of Utility Model Patent

Certificate of Invention Patent


Certificates of the Registration for Integrated Circuit Layout Designs

Strategic Partners

NXP · ST · Texas Instruments · AMD · Renesas · Allwinner · nuvoTon · Rockchip · DigiKey · Mouser Electronics

Our Clients (Part)

许继集团 · NARI 南瑞集团 · 国家电网公司 State Grid · Honeywell · GE Lighting · Panasonic 松下电器 · SIEMENS 西门子 · PHILIPS 飞利浦 · Johnson Controls · Schneider Electric

R&D Capabilities

MYIR has established R&D centers in both Shenzhen and Wuhan, and boasts a senior technical R&D team. Approximately 45% of our personnel are dedicated to R&D, and all of them possess a bachelor's degree or higher. The core and backbone members of our R&D team possess extensive experience in the embedded industry, having accumulated more than 10 years of professional expertise in the field. They are equipped with cutting-edge design concepts and practices specially tailored for high-volume product applications. Our products exhibit industry-leading innovation, reliability, and stability, and we have filed for numerous patents, copyrights, and various certifications, exceeding a total of 100.

Excellent, Scientific, and Systematic R&D Management

Complete R&D Management

Adopting the IPD process management concept, combined with modern information system management tools

- Project Management
- Task Management
- Defect Management
- Review Management
- Design Documentation
- Code Management
- Knowledge and Experience Management

Design Capability Optimization

Establish complete and unified key design node control

- Test Example
- Schematic/ PCB CheckList
- Standard Circuit Library
- DFX Management
- High-speed Signal Design and Simulation
- Material AVL Preferred Library

Technology and Skills

Hardware Development

- Standard Component Library
- Standard Circuit Diagram
- Complete Schematic (PCB CheckList)
- FMEA Analysis
- SI Simulation Design

Software Development

- Multiple OS Development Capabilities (Linux | android | RTOS)
- Kernel Porting and Driver Development Capabilities
- System Optimization Capabilities (boot time, real-time performance, multi-system backup, OTA, security, etc.)
- System Customization Capabilities Conform to Industrial and Power scenarios
- Protocol Development and Application Development Capabilities

Testing Capability

The MYIR R&D and testing team adheres to a scientific, rigorous, objective and fair attitude, relying on a comprehensive testing system and professional, extensive testing experience. All products are strictly tested in accordance with relevant national standards, industry standards, and company standards, ensuring that all the product has long-term stability, reliability, mass production capability, and data traceability.

Signal Test

Standards Range

- Corresponding chip data manual

Main Evaluation Items

Power Test

- ✓ Ground Impedance Test
- ✓ Ripple Test
- ✓ Up-down Waveform Test
- ✓ Power On/Off Timing Test
- ✓ Power Consumption Test
- ✓ Power Noise Test

Signal Test

- ✓ I2C Test
- ✓ I2S Test
- ✓ SDIO Test
- ✓ Clock Test
- ✓ Ethernet Test
- ✓ UART Test
- ✓ CAN Test
- ✓ RS232/RS485 Test

EMC Test

Standards Range

- EN55032
- NB/T33008.1
- IEC61000-4
- GB/T 17626

Main Evaluation Items

EMI: Electromagnetic Interference

- ✓ RE: Radiation Emission
- ✓ CE: Conducted Emissions
- ✓ Harmonics: Harmonic Current
- ✓ Flicker: Flashing

EMS: Electromagnetic Sensitivity

- ✓ RS: Radiation Immunity
- ✓ CS: Conducted Immunity
- ✓ ESD: Electrostatic Immunity
- ✓ Surge: Surge Immunity
- ✓ EFT/B: Electric Fast Transient Pulse Group
- ✓ PMS: Power Frequency Magnetic Field Anti-interference Degree
- ✓ Dips: Voltage Drop/ Short Interruption

Certification

Standards Range

- EN 55032: 2015
- EN 61000-3-3: 2013
- EN 55035: 2017
- EN IEC 61000-3-2: 2019
- IEC62321

Main Evaluation Items

- ✓ CE Certification
- ✓ RoHS Certification

Reliability Test

Standards Range

- GB/T 2423.2-2008
- GB/T 2423.8-1995
- GB/T 2423.17-2008
- GB/T 2423.22-2012
- GB/T 2423.10-2019
- GB/T 19056-2012
- GB/T 2423.5-2019

Main Evaluation Items


High Temperature Test


Aging Test


Vibration Testing


Shock Test


Salt Spray Test


MTBF Test

Technical Services

MYIR is customer-oriented, and provides comprehensive technical support and services for various issues encountered by customers during the processes of project selection, project approval, project development, product testing, small-batch trial production, and mass production. The company's frontline engineering team assists customers in solving technical problems through various channels such as online communication, telephone, email, remote video conferencing, and on-site services, and provides abundant learning materials. MYIR is committed to accelerating the customer's development process, reducing the customer's development costs, ensuring the quality of the customer's products, and enhancing the competitiveness of the customer's products in the market.

Pre-sales Service

1. **Communication and Requirement Analysis**
   The technical service team actively and comprehensively participates in analyzing and understanding customer requirements.
2. **Consultative Product Selection Guidance**
   Our professional team recommends the most suitable SOM optimized for performance, functionality, and cost-effectiveness.
3. **Software and Hardware Framework Construction**
   We ensure that the overall software and hardware system design aligns with and fulfills the customer's specific requirements.
4. **Prototype Verification**
   We ensure the feasibility and stability of the system design for the selected platform.
5. **Project Technical Risk Assessment**
   We identify potential risks, propose effective solutions, and formulate countermeasures.

In-sales Service

1. **Developer Resources Download**
   Provide detailed documentation and software packages for products.
2. **Schematic and PCB Design Guidance**
   Ensure that the circuit design layout is reasonable and meets system performance and stability requirements.
3. **Schematic and PCB Review**
   Avoid potential circuit board design issues and defects.
4. **Assist with Driver Development**
   Ensure compatibility between hardware and software, and verify the functionality and performance of underlying drivers.
5. **Assist with Middleware Porting**
   Ensure the normal operation and functional integrity of the system.
6. **Assist with System Optimization and Cropping**
   Improve system performance and stability while reducing resource consumption.
7. **Material Selection Guidance**
   Provide suggestions on quality, performance, and pricing to enhance product competitiveness.
8. **Test Plan Guidance**
   Ensure the project meets quality standards before launch and guarantee product stability.
9. **Production Process Guidance**
   Provide production process guidance documents as a reference to ensure product efficiency and quality.
10. **R&D Sampling Service**
    Provide one-stop sampling services and reports, analyze potential issues, and provide improvement suggestions.

After-sales Service

1. **Technical Support**
   Respond to customer queries in a timely manner, primarily providing support through emails, phone calls, or online meetings.
2. **Problem Recording and Organization**
   Maintain separate records for each customer issue to track the root cause and implement continuous improvement measures.
3. **Warranty**
   Offer product repair and exchange services. MYIR's production system ensures batch traceability at both the product and material levels, facilitating problem identification, analysis, resolution, as well as the provision of analysis reports and usage suggestions.
4. **Knowledge Sharing**
   Aid customers in enhancing their understanding of product usage through articles, documentation and videos.
5. **Output 8D report**
   The report encompasses a comprehensive analysis, including problem description, root cause analysis, corrective actions, preventive measures, and improvement suggestions.

Quality Assurance

MYIR has implemented a series of inspection steps, including incoming inspection of materials, pre-assembly baking, solder paste printing inspection, online AOI, first article inspection, spot X-RAY inspection, IPQC patrol inspection, and QA outgoing inspection. We also conduct comprehensive real-time electrostatic protection monitoring. By adhering to the ISO9001 quality management system, we ensure a high product qualification rate for all outgoing products.

1 Project Management

Project initiation, PCB design, layout review, trial production summary, and transition to mass production review and summarize meetings to ensure the smooth transition of the project.

2 Incoming Materials Inspection

Material recognition, sample sealing, incoming inspection (appearance, function) to ensure raw material quality

3 Process Control

Track and inspect the factory production line, conduct sampling of finished products, timely feedback on production abnormalities, and track process improvement confirmations to ensure process quality

4 QA Outgoing Inspection

Conduct QA inspection, finished product sampling, packaging inspection to ensure finished product quality

5 Customer Feedback

Hold timely and effective customer complaint meetings, conduct root cause investigations and improvements, confirm effectiveness. Follow up with customers, adhering to customer-first principles

Systematic Warehouse Management

The warehouse uses X-ray automatic component counting machines and AI-enabled intelligent sensing shelves. For the electronic components warehouse, it maintains a controlled temperature and humidity, incorporates anti-static measures, and strictly adheres to a first-in-first-out inventory management protocol. It supports the issuance of materials for multiple work orders, enables real-time inventory tracking, prevents material loss and errors, seamlessly integrates with MES and ERP systems, and ensures traceability throughout the entire process of usage and management.

WMS Intelligent Warehousing System

Intelligent shelves, combined with a smart warehouse system, achieve zero material error.

Constant Temperature and Constant Humidity, Ensuring Safety

Integrated circuits and electronic components are stored in warehouses and cabinets maintained at constant temperature and humidity to ensure the effectiveness and reliability of materials.

A Complete Supply Chain System

We have a senior supply chain management team with over 10 years of industry experience. We offer comprehensive BOM material supply, component selection, and substitute recommendation services. With professional BOM engineers and strict, standardized IQC incoming material inspection standards, as well as original genuine product guarantees sourced from original manufacturers and primary agents, we ensure that we provide our customers with short delivery times, high-quality, and low-price component guarantees.

1,000+ Original Manufacturers and Agent Cooperation Partners (including some of them)

Production Capacity

MYIR has a 3,000-square-meter smart SMT factory, equipped with a Class 100,000 cleanroom and multiple SMT production lines. Leveraging advanced production equipment, sophisticated management systems, stringent quality control processes, a comprehensive supply chain network, and robust engineering support, we guarantee product quality throughout the entire process, from raw material sourcing to production and ultimately shipping. Our factory possesses a surface mount capability of over 5 million points per day, and all production processes adhere strictly to RoHS and REACH standards.

Complete Automated Production Equipment

Equipped with Panasonic imported high-speed dual-track SMT line, our factory has fully automatic solder paste printer, nitrogen reflow oven, wave soldering machine, AOI, SPI and X-RAY inspection machines, intelligent first article inspection instrument, intelligent solder paste management cabinet, automatic PCB router machine, conformal coating machine, laser engraving machine, BGA rework stations, and other equipment. It is also supported by MES intelligent management system, intelligent warehousing system, ERP system, and static electricity management system.

Automatic Solder Paste Printer

Automatic Solder Paste Inspection Machine (3D SPI)

NPM-D3A SMT Machine

NPM-TT2 SMT Machine

Online AOI

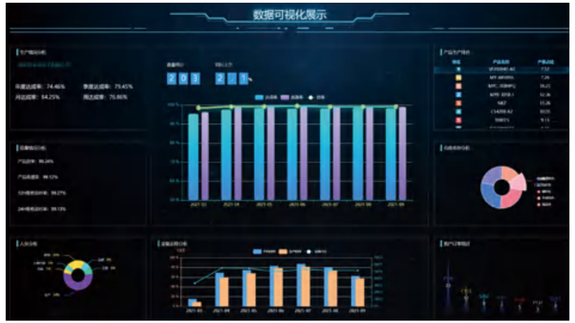
Automatic Coating Production Line

Excellent Production Environment Conditions

The production workshop equipment and assembly line stations are equipped with LoRa electrostatic monitoring nodes. If the electrostatic levels exceed the standard, audible and visual alarms will be triggered. The real-time data collected by the gateway will be transmitted to the data backend. Overall electrostatic data from the workshop can be dynamically displayed on a large screen in multiple dimensions.

Integrated Manufacturing Information Management System

An industry-leading integrated manufacturing information management system (MES) that enables seamless integration with ERP, WMS, SRM and other systems, improving the real-time nature and transparency of factory management, as well as the level of full-process traceability and error prevention control for products.



Naming Convention

MY: MYIR
Manufacturer

SOM Interface
LCC (Leadless Chip Carriers, Castellated-hole)
LGA (Land Grid Array)
MXM (Mobile PCI Express Module, Gold-finger)

- Y: LCC/LCC+LGA
- C: B2B Connector
- J: MXM
- L: LGA
- No Character: SBC

Product Version
- No Character: V1 Version
- V2: V2 Version

RAM Capacity
- 2D: 2GB DDR
- 1D: 1GB DDR
- 512D: 512MB DDR
- 256D: 256MB DDR

Temperature Grade (C, E, I)
- C: Commercial (0 °C~+70 °C)
- E: Extended (-20 °C~+70 °C)
- I: Industrial (-40 °C~+85 °C)

M Y D - Y G 2 L 2 3 - V 2 - 8 E 2 D - 1 2 0 - I - X

Product Category
- B: Base Board
- C: SOM
- D: Development Board
- S: Single Board Computer

Processor Model
- G2LX: RZ/G2L
- 335X: AM335X
- T113X: T113
- 6ULX: i.MX6UL

Where X is an explicit character, used to distinguish different chip models of the same series.

ROM Capacity
- E: eMMC
- 8E: 8GB eMMC
- 4E: 4GB eMMC
- N: Nand Flash
- 256N: 256MB Nand Flash
- 512N: 512MB Nand Flash

CPU Clock Speed (Max)
- 120: 1.2GHz
- 80: 800MHz
- 65: 650MHz

Special Identification
- No Character: No Special Identification
- B: With Enclosure
- G: Material Difference
- FAN: With Heatsink

SOM Selection Table

Performance \ CPU Vendor	ST	NXP	AMD XILINX	TI
Entry-level A7/A8/A9/ A55/FPGA 1-2 Cores	**MYC-YF13X** P20 ST STM32MP135 A7@1.0GHz 2×1000M ETH, 8×UART, Parallel CSI 2×CAN FD, Parallel LCD	**MYC-Y6ULX-V2** P24 NXP i.MX6UL/i.MX6ULL A7@528MHz 2×100M ETH, 2×CAN, 8×UART Parallel LCD, Parallel CSI	**MYC-J7A100T** P30 AMD-Xilinx Artix 7A100T FPGA: 101K 2×1000M ETH, HDMI, UART Camera, 2×SFP, PCIE2.0	**MYC-C335X-V4** P35 TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD
	MYC-YA15XC-T P21 ST STM32MP151 A7@650MHz+M4@209MHz 1000M ETH, 8×UART Parallel LCD, Parallel CSI		**MYC-C/Y7Z010/20-V2** P31 AMD-Xilinx XC7Z010/20 ARM: 2×A9@667MHz/766MHz, FPGA: 28K/ 85K 1000M ETH, LCD, USB2.0, CAN UART	**MYC-Y335X-V2** P36 TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD
	MYC-YA157C-V3 P22 ST STM32MP157 2×A7@650MHz+M4@209MHz 1000M ETH, 8×UART, MIPI DSI 2×CAN FD, 3D GPU		**MYC-C7Z015** P33 AMD-Xilinx XC7Z015 ARM: 2×A9@766MHz FPGA: 74K 1000M ETH, LCD, USB2.0, CAN UART, PCIE2.0, SFP	
Mid-range A35/A53/A55 2-4 Cores	**MYC-LD25X** P23 ST STM32MP257 2xA35@1.5GHz+M33@400MHz 3x1000M ETH, 4×USART, MIPI DSI, 5×UART, 3×CAN FD, Parallel RGB	**MYC-LMX9X** P25 NXP i.MX93 2×A55@1.7GHz+M33@250MHz 2×1000M ETH, 2×CAN FD, 8×UART LVDS, MIPI DSI, MIPI CSI		
		MYC-C8MMX-V2 P26 NXP i.MX 8M Mini 4×A53@1.8GHz+M4@400MHz 1×1000M ETH, 4×UART, 1×PCIE2.0 MIPI DSI, MIPI CSI, 3D GPU, VPU		
High-end A53/A55/A72 2-8 Cores		**MYC-JX8MPQ** P27 NXP i.MX 8M Plus 4×A53@1.8GHz+M7@800MHz 2×1000M ETH, 2×CAN FD, PCIE2.0, 2×USB3.0, NPU, MIPI DSI, HDMI	**MYC-CZU3EG/4EV/5EV-V2** P34 AMD-Xilinx XCZU3EG/4EV/5EV ARM: 4xA53@1200MHz+2xR5@600MHz FPGA: 154K(3EG)/192K(4EV)/256K(5EV) 1000M ETH, CAN, LCD, USB3.0 FMC, DP, SATA3.0, UART, PCIE2.0	
		MYC-J1028X P28 NXP LS1028A 2×A72@1.5GHz 2×1000M ETH, DP1.3/eDP1.4, SATA 3.0 2×USB3.0, 2×PCIE3.0, 4×TSN Switch		
		MYC-JX8MMA7 P29 NXP i.MX 8M Mini+AMD Artix 7 ARM: 4×A53@1.8GHz+M4@400MHz, FPGA: 23K 1000M ETH, 2×USB2.0, 4×UART, 3×SPI, MIPI DSI, MIPI CSI		

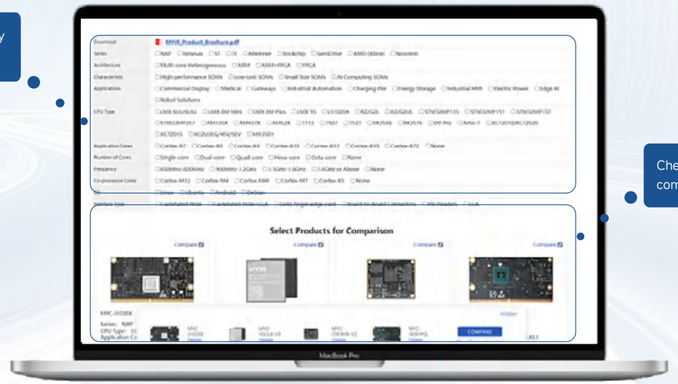
SOM Selection Table

Performance \ CPU Vendor	Renesas	Allwinner	SemiDrive	Nuvoton	Rockchip
Entry-level A7/A8/A9/ A55/FPGA 1-2 Cores	**MYC-YG2UL** P41 Renesas RZ/G2UL A55@1.0GHz+M33@200MHz 2×1000M ETH, 2×USB2.0, 1×MIPI CSI 7×UART, 2×CAN FD, 3×SPI, 1×RGB	**MYC-YT113i** P43 Allwinner T113-i 2×A7@1.2GHz 1000M ETH, 6×UART, Parallel CSI MIPI DSI, RGB, 2×LVDS, 2×CAN			
		MYC-YT113X P44 Allwinner T113-S3 2×A7@1.2GHz 1000M ETH, 6×UART, Parallel CSI MIPI DSI, RGB, 2×LVDS, 2×CAN			
Mid-range A35/A53/A55 2-4 Cores	**MYC-YG2LX** P42 Renesas RZ/G2L 2×A55@1.2GHz+M33@200MHz 2×1000M ETH, 2×USB2.0, 7×UART, 2×CAN FD, 3D GPU, VPU, MIPI DSI	**MYC-LT536** P45 Allwinner T536 4×A55@1.6GHz+RISCV@600MHz 2×1000M ETH, 17×UART, 4×I2S 4×USB2.0, Localbus, 4×CAN FD		**MYC-LMA35** P49 Nuvoton MA35D1 2×A35@800MHz+M4@180MHz 2×1000M ETH, 4×CAN FD, 17×UART 16bit EBI, 24bit RGB, 2×USB2.0	**MYC-LR3568** P50 Rockchip RK3568 4×A55@2.0GHz 2×1000M ETH, 2×HDMI, 2×MIPI CSI eDP1.3, 4×USB, 2×PCIe3.0, SATA3.0
		MYC-YT507H P46 Allwinner T507-H 4×A53@1.5GHz 1000M ETH, 1×FE, 6×UART 4×USB2.0, 2×LVDS, RGB, 3D GPU			
High-end A53/A55/A72 2-8 Cores		**MYC-LT527** P47 Allwinner T527 8×A55@1.8GHz+RISC-V@200MHz 2×1000M ETH, HDMI, MIPI DSI/CSI 3×USB, 2×CAN, 10×UART, 4×SPI	**MYC-JD9360** P48 SemiDrive D9360 6×A55@1.6GHz+R5@800MHz 2×1000M ETH, 2×USB3.0, 2×PCIe3.0 4×CAN FD, 8×SPI, 12×I2C, 8×PWM		**MYC-LR3576** P51 Rockchip RK3576 4xA72@2.2GHz+4xA53@1.8GHz 2×1000M ETH, PCIE, USB3, SATA3, DSMC/FlexBus, 2×CAN FD, 12×UART

MYIR Products Selection Site

https://en.myir.cn/Select.html

Filter product categories to quickly locate specific category products.



Check 2 to 4 SOMs to compare specific parameters.

Advantages of MYIR's System-On-Modules

Innovative Design

LCC/LGA Packaging

Ensures more stable and reliable signal connection, superior vibration resistance, and convenience for mass production

Shield Design

Resistant to signal interference and dust, while supporting customized LOGO to enhance customer brand value

Compact Design

Features a small size and flexible design, making it suitable for various sizes of products, especially those with limited structural space

Excellent Quality

Rigorous Testing

The SOMs undergo six rigorous tests, including signal tests, high and low temperature tests, aging tests, electrostatic tests, over 5,000 power-on and power-off tests, and MTBF tests, to ensure product stability.

Compliance with International Certification Standards

Adopting international SGS as a certification testing partner, we provide CE and RoHS certification reports

Smart Factory

MYIR's own factory, equipped with advanced production equipment and adopting MES systems, ensures high-quality and traceability of products

Competitive cost

Scale Effect

With over one million SOMs sold annually, we achieve excellent bulk material costs through mass production

Packaging Advantage

The SOMs adopt an LCC/LGA packaging design, which saves the cost of board-to-board connectors

Supply Chain Management

Establishing close cooperation relationships with original manufacturers enables us to obtain more competitive chip price support

Advantages of MYIR's System-On-Modules

Quick Delivery and Long Lifecycle

Short lead time

By implementing a comprehensive inventory management system for our standard products, we guarantee a shortened lead time for both sample and bulk orders.

Long lifecycle

We guarantee a supply duration exceeding 10 years. In case of material discontinuation, we have established a comprehensive product change process and notification policy to mitigate any potential disruptions.

Long-term maintenance

Our commitment extends to providing ongoing software maintenance and regular updates for the BSP package, ensuring its continued reliability and performance over time.

Full-service technical support

Pre-sales service

We offer optimal platform recommendations, feasibility assessments, software and hardware framework setups, and prototype function verifications during the selection phase, guiding you through the initial stages of your project seamlessly.

In-sales service

During the design phase, we provide schematic diagram and PCB guidance and review, driver debugging, middleware transplantation, and system optimization, ensuring the smooth progress of your development efforts.

After-sales service

We maintain prompt email communication with our FAE team, offering remote assistance to resolve any issues that may arise. We document the entire process and provide an 8D report, ensuring transparency and continuous improvement.

Abundant development resources

Hardware documentation

Comprehensive product manuals, hardware design guides, hardware user manuals, and pin usage tables for our SOMs, facilitating easy integration and customization.

Software documentation

Detailed quick start guides, software development guides, software evaluation guides, and application notes, enabling efficient software development and deployment.

Design materials

Access to our baseboard schematic and PCB source files, BSP software source code, and industry application demos, providing a solid foundation for your design and development efforts.

MYC-YF13X

- ST STM32MP135 Processor, Cortex-A7@1.0GHz
- DDR3L, Nand Flash/eMMC, EEPROM
- LCD-TFT Parallel Display Interface, 16-bit Camera, 2x USB2.0, 2x CAN-FD, 2x Gigabit Ethernet
- 37mm x 39mm; LCC Package, 148-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

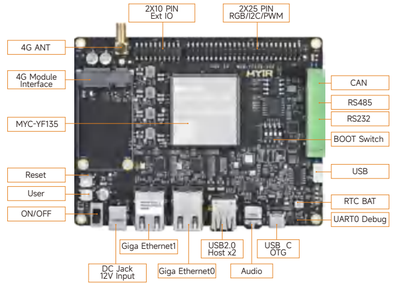
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YF135-256N256D-100-I	STM32MP135DAF7	Cortex-A7@1.0GHz	256MB DDR3	256MB Nand Flash	32Kbit EEPROM	LCC 148PIN	-40°C~+85°C	37mm x 39mm	Linux	MYD-YF135-256N256D-100-I
MYC-YF135-4E512D-100-I			512MB DDR3	4GB eMMC						MYD-YF135-4E512D-100-I

Peripherals/Interfaces

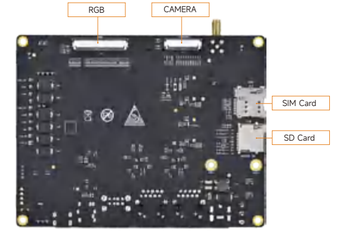
Communications	2×RGMII, 2×CAN FD, 2×USB2.0, 8×UART, 5×SPI, 5×I2C
Multimedia	RGB, DCMI, 2×SAI, 3×I2S
Others	12-bit 19-ch ADC, 12-bit 18-ch ADC, SWD

Key Applications

Industrial HMI | Industrial Gateway | Industrial Control | Power Management



MYD-YF13X Development Board Top-view



MYD-YF13X Development Board Bottom-view

MYC-YA15XC-T

- ST STM32MP151 Processor, Cortex-A7@650MHz + Cortex-M4@209MHz
- DDR3L, Nand Flash/eMMC, EEPROM
- Gigabit Ethernet, 2x USB 2.0, 8x UART, 6x SPI, 6x I2C
- 37mm x 39mm; LCC Package, 148-pin; 0 to 70 °C Commercial, -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

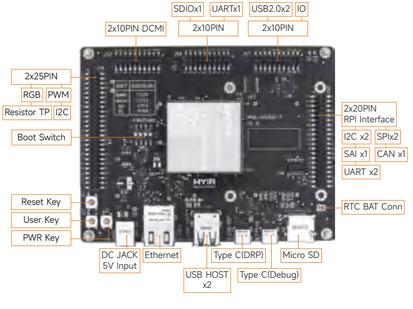
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YA151C-256N256D-65-C-T	STM32MP151AAC3	Cortex-A7@650MHz +Cortex-M4@209MHz	256MB DDR3	256MB Nand Flash	32Kbit EEPROM	LCC 148PIN	0°C~+70°C	37mm × 39mm	Linux	MYD-YA151C-V2-256N256D-65-C-T
MYC-YA151C-256N256D-65-I-T							-40°C~+85°C			MYD-YA151C-V2-256N256D-65-I-T
MYC-YA151C-4E512D-65-C-T			512MB DDR3	4GB eMMC			0°C~+70°C			MYD-YA151C-4E512D-65-C-T
MYC-YA151C-4E512D-65-I-T							-40°C~+85°C			MYD-YA151C-4E512D-65-I-T

Peripherals/Interfaces

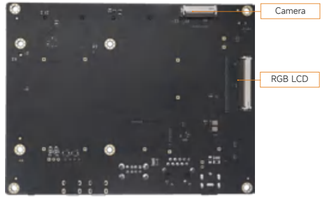
Communications	RGMII, 2×USB2.0, 8×UART, 6×SPI, 6×I2C
Multimedia	RGB, DCMI, 4×SAI, 3×I2S
Others	2×16-bit 20-ch ADC, SWD

Key Applications

HMI | Medical Device | Industrial Manufacturing | Petroleum & Chemical



MYD-YA15XC-T Development Board Top-view



MYD-YA15XC-T Development Board Bottom-view

MYC-YA157C-V3

- ST STM32MP157 Processor, 2x Cortex-A7@650MHz + Cortex-M4@209MHz
- DDR3, eMMC, Ethernet PHY
- Gigabit Ethernet, 2x CAN, 2x USB2.0, 8x UART, 6x SPI, 6x I2C
- 43mm x 45mm; LCC Package, 164-pin; 0 to 70 °C Commercial, -40°C~+85°C Industrial; Linux / Ubuntu OS

Part Selections (Other Configurations can be Customized for Mass Production)

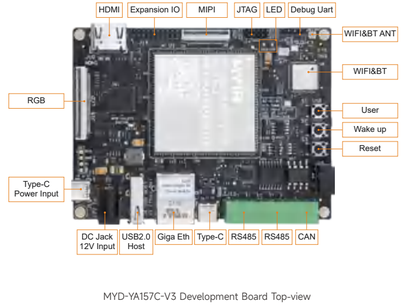
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YA157C-V3-4E512D-65-C	STM32MP157AAC3	2×Cortex-A7@650MHz +Cortex-M4@209MHz	512MB DDR3L	4GB eMMC	Ethernet PHY	LCC 164PIN	0°C~+70°C	43mm x 45mm	Linux Ubuntu	MYD-YA157C-V3-4E512D-65-C
MYC-YA157C-V3-4E512D-65-I							-40°C~+85°C			MYD-YA157C-V3-4E512D-65-I

Peripherals/Interfaces

Communications	RGMII, 2×CAN FD, 2×USB2.0, 8×UART, 6×SPI, 6×I2C
Multimedia	RGB, MIPI DSI, 4×SAI, 3×I2S
Others	2×16-bit 20-ch ADC, SWD

Key Applications

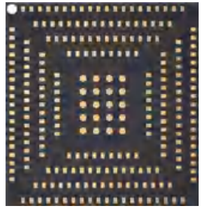
HMI | Medical Device | Industrial Manufacturing | Petroleum & Chemical



MYD-YA157C-V3 Development Board Top-view

MYD-YA157C-V3 Development Board Bottom-view

MYC-LD25X



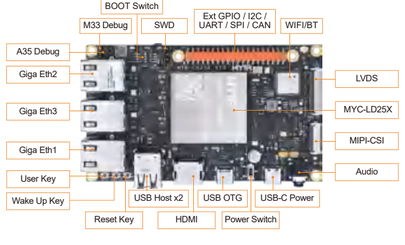
- ST STM32MP257D, 2x Cortex-A35@1.5GHz + Cortex-M33@400MHz
- LPDDR4, eMMC, EEPROM
- Neural Processing Unit (NPU) operating at up to 1.35 TOPS, 3D GPU
- 3x Gigabit Ethernet, 3x CAN FD, USB3.0, 5x UART, 8x SPI, 7x I2C
- 39mm x 37mm; LGA Package, 252-pin; -40°C~+85°C Industrial; Linux / Debian

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LD257-8E1D-150-I	STM32MP257DAK3	2×Cortex-A35@1.5GHz+ Cortex-M33@400MHz	1GB LPDDR4	8GB eMMC	256Kbit EEPROM	LGA 252PIN	-40°C~+85°C	39mm × 37mm	Linux Debain	MYD-LD257-8E1D-150-I
MYC-LD257-8E2D-150-I			2GB LPDDR4							MYD-LD257-8E2D-150-I

Peripherals/Interfaces

Communications	3xRGMII, USB2.0 HOST, USB3.0 OTG/PCIE2.0, 4xUSART, 5×UART, 8×SPI, 7×I2C, 4×I3C, 3×CAN FD, 2×SD/MCC
Multimedia	Parallel RGB, MIPI DSI, LVDS, MIPI CSI , DCMI, 4xSAI
Others	JTAG, SWD



MYD-LD25X Development Board Top-view

MYD-LD25X Development Board Bottom-view

Key Applications

Industrial HMI | Edge Computing Gateway | New Energy Charging Pile | Energy Storage EMS Systems

MYC-Y6ULX-V2

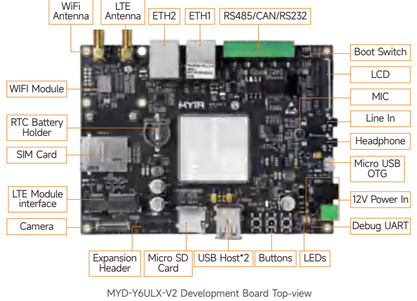
- NXP i.MX 6UL/i.MX 6ULL Processor, Cortex-A7@528MHz
- DDR3, Nand FLASH/eMMC, On-board Gigabit Ethernet PHY
- 2x USB2.0, 2x 10/100Mbps Ethernet, 2x CAN, 8x UART, 4x SPI, 4x I2C
- 37mm x 39mm; LCC Package, 140-pin; 0°C~+70°C Commercial; -40°C~+85°C Industrial;
- Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-Y6ULY2-V2-256N256D-50-C	MCIMX6Y2CVM05AB	Cortex-A7@528MHz	256MB DDR3	256MB Nand FLASH	Ethernet PHY	LCC 140PIN	0°C~+70°C	37mm x 39mm	Linux	MYD-Y6ULY2-V2-256N256D-50-C
MYC-Y6ULY2-V2-256N256D-50-I							-40°C~+85°C			MYD-Y6ULY2-V2-256N256D-50-I
MYC-Y6ULY2-V2-4E512D-50-C			512MB DDR3	4GB eMMC			0°C~+70°C			MYD-Y6ULY2-V2-4E512D-50-C
MYC-Y6ULY2-V2-4E512D-50-I							-40°C~+85°C			MYD-Y6ULY2-V2-4E512D-50-I
MYC-Y6ULG2-V2-256N256D-50-I	MCIMX6G2CVM05AB		256MB DDR3	256MB Nand FLASH						MYD-Y6ULG2-V2-256N256D-50-I

Peripherals/Interfaces

Communications	2×RMII, 2×CAN, 2×USB2.0, 8×UART, 4×SPI, 4×I2C
Multimedia	RGB, Parallel CSI , 3×I2S
Others	2×12bit 10ch ADC, JTAG



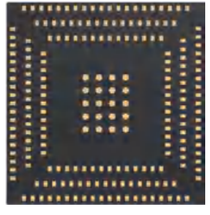
MYD-Y6ULX-V2 Development Board Top-view

Key Applications

Charging Pile | HMI | Industrial Control | Medical Device

NXP | MYC-LMX9X

- NXP i.MX 93 Processor, 2*Cortex-A55@1.7GHz + Cortex-M33@250MHz
- 0.5 TOPS NPU for Cost-effective and Energy-efficient ML Applications
- 2x Gigabit Ethernet (one TSN-based), 2x CAN FD, 8x UART, 8x I2C, 8x SPI
- LPDDR4, eMMC, EEPROM, 37mm x 39mm; LGA Package, 218-pin; -40°C~+85°C Industrial
- Linux OS (Yocto based with QT / Debian)



Part Selections (Other Configurations can be Customized for Mass Production)

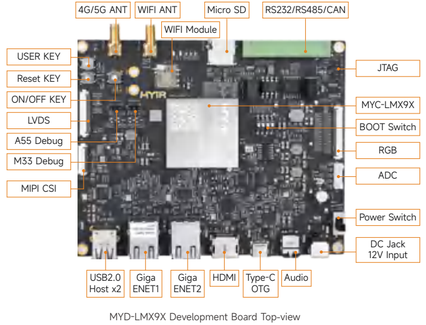
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LMX9352-8E1D-170-I	MIMX9352CVVXMAB	2×Cortex-A55@1.7GHz+ Cortex-M33@250MHz	1GB LPDDR4	8GB eMMC	32KB EEPROM	LGA 218PIN	-40°C~+85°C	37mm x 39mm	Linux Debian	MYD-LMX9352-8E1D-170-I
MYC-LMX9352-8E2D-170-I			2GB LPDDR4							MYD-LMX9352-8E2D-170-I

Peripherals/Interfaces

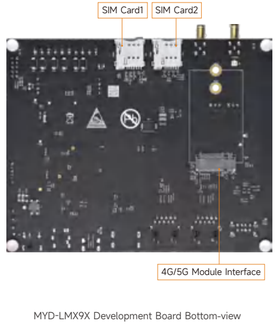
Communications	2×RGMII, 2×CAN FD, 2×USB2.0, 8×UART, 8×SPI, 8×I2C, 2×I3C
Multimedia	MIPI DSI, LVDS, RGB, MIPI CSI, Parallel CSI , 3×SAI
Others	12bit 4ch ADC, JTAG

Key Applications

Charging Pile | Motion Controller | Engineering Machinery | Medical Device



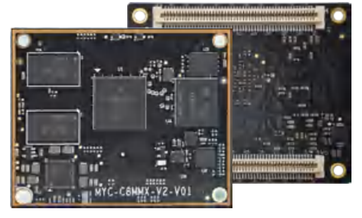
MYD-LMX9X Development Board Top-view



MYD-LMX9X Development Board Bottom-view

NXP | MYC-C8MMX-V2

- NXP i.MX 8M Mini Processor, 4*Cortex-A53@1.8GHz + Cortex-M7@400MHz
- DDR4, eMMC, QSPI Flash, On-board Gigabit Ethernet PHY
- 2x USB2.0, Gigabit Ethernet, PCIE2.0, 4x UART, 3x SPI, 3x I2C
- 49mm x 60mm; 200-pin Board-to-Board Connectors; 0°C~+70°C Commercial; -40°C~+85°C Industrial
- Linux / Android OS



Part Selections (Other Configurations can be Customized for Mass Production)

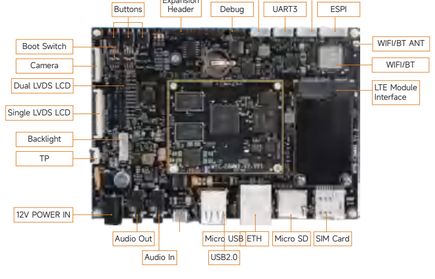
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C8MMQ6-V2-8E2D-180-C	MIMX8MM6DVTLZAA	4×Cortex-A53@1.8GHz +Cortex-M4@400MHz	2GB DDR4	8GB eMMC	Ethernet PHY 32MB QSPI FLASH	B2B 200PIN	0°C~+70°C	49mm × 60mm	Linux Android	MYD-C8MMQ6-V2-8E2D-180-C
MYC-C8MMQ6-V2-8E2D-160-I	MIMX8MM6CVTKZAA	4×Cortex-A53@1.6GHz +Cortex-M4@400MHz					-40°C~+85°C			MYD-C8MMQ6-V2-8E2D-160-I

Peripherals/Interfaces

Communications	RGMII, PCIE2.0, 2×USB2.0, 4×UART, 3×SPI, 3×I2C
Multimedia	MIPI DSI, MIPI CSI, 5×SAI
Others	JTAG

Key Applications

Commercial HMI | Medical Device | Industrial Control | Artificial Intelligence



MYD-C8MMX-V2 Development Board Top-view

MYD-C8MMX-V2 Development Board Bottom-view

NXP | MYC-JX8MPQ

- NXP i.MX 8M Plus Processor, 4*Cortex-A53@1.6GHz + Cortex-M7@800MHz
- 2.3 TOPS NPU for Extensive AI/ML Capabilities; 800MHz Audio DSP, Dual Camera Interfaces (ISP), 3D GPU
- LPDDR4, eMMC, QSPI Flash; 2x USB3.0, 2x Gigabit Ethernet, 2x CAN FD, 4x UART, 3x SPI, 6x I2C
- 45mm x 82mm; MXM Package, 314-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

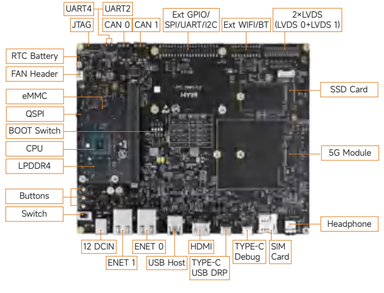
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-JX8MPQ-8E2D-160-I	MIMX8ML8CVNKZAB	4×Cortex-A53@1.6GHz +Cortex-M7@800MHz	2GB LPDDR4	8GB eMMC	32MB QSPI FLASH	MXM 314PIN	-40°C~+85°C	45mm x 82mm	Linux	MYD-JX8MPQ-8E2D-160-I
MYC-JX8MPQ-8E4D-160-I			4GB LPDDR4							MYD-JX8MPQ-8E4D-160-I

Peripherals/Interfaces

Communications	2×RGMII, PCIE3.0, 2×USB3.0, 2×CAN FD, 4×UART, 3×SPI, 6×I2C
Multimedia	HDMI, MIPI-DSI, LVDS, 2×MIPI CSI, 6×SAI
Others	JTAG

Key Applications

HMI | High-performance AI Devices | Industrial Computers | Edge Computing



MYD-JX8MPQ Development Board Top-view

MYD-JX8MPQ Development Board Bottom-view

NXP | MYC-J1028X

- NXP LS1028A Processor, 2*Cortex-A72@1.5GHz, DDR4, eMMC, EEPROM
- 6x Gigabit Ethernet (TSN-based), 2x USB3.0, 2x CAN FD, 6x UART, 3x SPI, 1x SATA3.0
- Support DP Display (DP1.3 and eDP 1.4, resolution up to 4K@60FPS)
- 45mm x 82mm; MXM 3.0 Gold-finger Interface, 314-pin; -40°C~+85°C Industrial;
- Supports Ubuntu and Real-time Edge Images based on Linux

Part Selections (Other Configurations can be Customized for Mass Production)

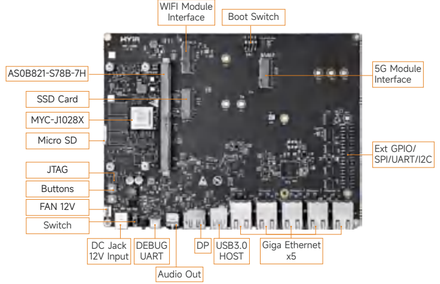
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-J1028N-8E2D-150-I	LS1028AXN7PQA	2×Cortex-A72@1.5GHz	2GB DDR4	8GB eMMC	32Kbit EEPROM	MXM 314PIN	-40°C~+85°C	45mm x 82mm	Linux Ubuntu	MYD-J1028N-8E2D-150-I

Peripherals/Interfaces

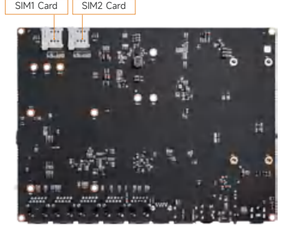
Communications	SGMII, QSGMII, RGMII, 2×PCIE3.0, SATA 3.0, 2×USB3.0, 2×CAN FD, 6×UART, 3×SPI, 8×I2C
Multimedia	eDP, 6×SAI
Others	JTAG

Key Applications

Automotive Electronics | Industrial Routers | Industrial Control | Edge Computing



MYD-J1028X Development Board Top-view



MYD-J1028X Development Board Bottom-view

NXP & AMD | MYC-JX8MMA7

- i.MX 8M Mini + XC7A25T Aritx-7, 4*Cortex-A53@1.8GHz + Cortex-M4@400MHz + FPGA
- ARM: LPDDR4, eMMC, QSPI Flash; FPGA: DDR3, QSPI Flash
- Integrated 2D/3D GPU and 1080p VPU, Two PMIC (one for ARM and one for FPGA)
- 45mm x 82mm; MXM 3.0 Gold-finger Interface, 314-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

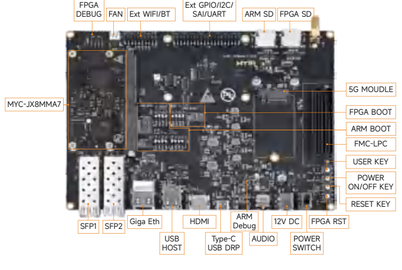
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-JX8MMA7-8E2D-32Q256D-160-I	ARM: MIMX8MM6CVTKZAA FPGA: XC7A25T-2CSG325I	4×Cortex-A53@1.6GHz+ Cortex-M4@400MHz FPGA: 23K	ARM: 2GB LPDDR4 FPGA: 256MB DDR3	ARM: 8GB eMMC FPGA: 32MB QSPI FLASH	32MB QSPI FLASH	MXM 314PIN	-40°C~+85°C	45mm x 82mm	Linux	MYD-JX8MMA7-8E2D-32Q256D-160-I
MYC-JX8MMA7-8E2D-32Q256D-180-C	ARM: MIMX8MM6DVTLZAA FPGA: XC7A25T-2CSG325C	4*Cortex-A53@1.8GHz+ Cortex-M4@400MHz FPGA: 23K					0°C~+70°C			MYD-JX8MMA7-8E2D-32Q256D-180-C

Peripherals/Interfaces

Communications	RGMII, 2×USB2.0, 4×UART, 2×SPI, 2×I2C, 3×GTP
Multimedia	MIPI DSI, MIPI CSI, 3×SAI
Others	JTAG

Key Applications

Data Acquisition | Medical Equipment | Industrial Control | Industrial Gateway



MYD-JX8MMA7 Development Board Top-view

MYD-JX8MMA7 Development Board Bottom-view

AMD XILINX | MYC-J7A100T

- AMD/Xilinx XC7A100T Artix-7 FPGA (XC7A100T-2FGG484I)
- DDR3, QSPI FLASH, EEPROM
- Supports Development by Xilinx's Vivado Design Suite
- 69.6mm x 40mm; MXM Package, 260-pin; -40°C~+85°C Industrial

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-J7A100T-32Q512D-I	XC7A100T-2FGG484I	-	512MB DDR3	32MB QSPI FLASH	32KB EEPROM	MXM 260PIN	-40°C~+85°C	69.6mm x 40mm	Xilinx's Vivado Design Suite	MYD-J7A100T-32Q512D-I

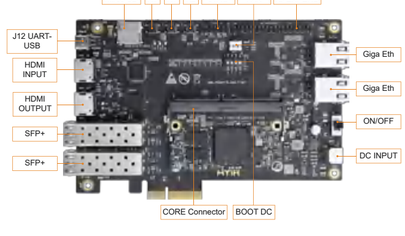
Signals Routed to Pins

0.5mm pitch MXM Gold-finger-edge-card Expansion Interface

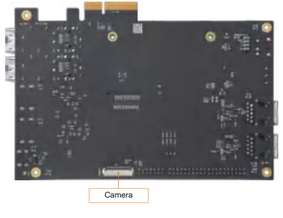
Item	Number of I/Os	Description
Bank13	35	There are 178 I/Os in total, which are defined according to different requirements. Signal lines with the same function are located on the same bank.
Bank14	45	
Bank15	48	
Bank16	50	
MGTP	20	High-Speed Serial Interfaces
JTAG	4	JTAG Debug

Key Applications

Communication | Computing | Industrial Control | Automotive



MYD-J7A100T Development Board Top-view



MYD-J7A100T Development Board Bottom-view

MYC-C7Z010/20-V2

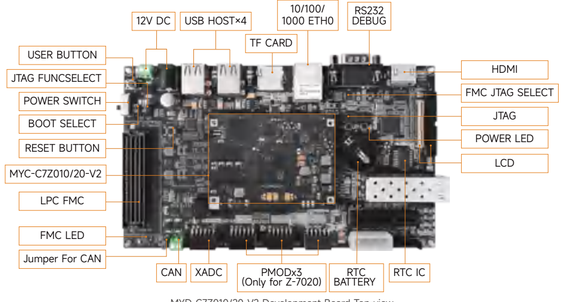
- Xilinx XC7Z010/20 Processor, 2x Cortex-A9@667/766MHz+Artix 7 FPGA
- DDR3, eMMC, QSPI Flash
- On-board Gigabit Ethernet PHY
- 75mm x 55mm; B2B Package, 2x140-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C7Z010-V2-4E1D-667-I	xc7z010-1clg400	2×Cortex-A9@667Hz +Atrix 7 FPGA （28K）	1GB DDR3	4GB eMMC	32MB QSPI Flash Ethernet PHY USB PHY	B2B 2×140PIN	-40°C~+85°C	75mm × 55mm	Linux	MYD-C7Z010-V2-4E1D-667-I
MYC-C7Z020-V2-4E1D-766-I	xc7z020-2clg400	2×Cortex-A9@766Hz +Atrix 7 FPGA （85K）								MYD-C7Z020-V2-4E1D-766-I
MYC-C7Z010-V2-4E1D-667-C	xc7z010-1clg400	2×Cortex-A9@667Hz +Atrix 7 FPGA （28K）					0°C~+70°C			MYD-C7Z010-V2-4E1D-667-C
MYC-C7Z020-V2-4E1D-766-C	xc7z020-2clg400	2×Cortex-A9@766Hz +Atrix 7 FPGA （85K）								MYD-C7Z020-V2-4E1D-766-C

Peripherals/Interfaces

Communications	RGMII, USB2.0, CAN, 2×SPI, 2x I2C, XADC
FPGA Expansion IO	141PIN (FPGA_XC7020) , 114PIN (FPGA_XC7010)

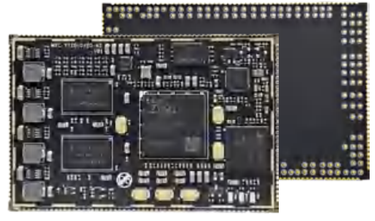


MYD-C7Z010/20-V2 Development Board Top-view

Key Applications

Automotive | Medical Device | Industrial Control | Communication Systems

MYC-Y7Z010/20-V2



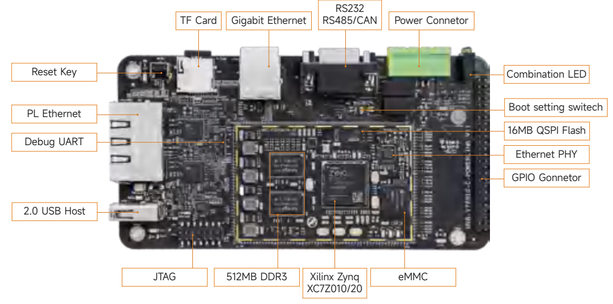
- Xilinx XC7Z010/20 Processor, 2x Cortex-A9@667/766MHz+Artix 7 FPGA
- DDR3, eMMC, QSPI Flash
- On-board Gigabit Ethernet PHY
- 75mm x 50mm; LCC Package, 180-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-Y7Z010-V2-4E512D-667-I	xc7z010-1clg400	2*Cortex-A9@667Hz +Atrix 7 FPGA （28K）	512MB DDR3	4GB eMMC	16MB QSPI Flash Ethernet PHY	LCC 180PIN	-40°C~+85°C	75mm × 50mm	Linux	MYD-Y7Z010-V2-4E1D-667-I
MYC-Y7Z020-V2-4E512D-766-I	xc7z020-2clg400	2*Cortex-A9@766Hz +Atrix 7 FPGA （85K）								MYD-Y7Z020-V2-4E1D-766-I

Peripherals/Interfaces

Communications	RGMII, USB2.0, CAN, 2×SPI, 2× I2C, JTAG
FPGA Expansion IO	Expandable 121PIN



MYD-Y7Z010/20-V2 Development Board Top-view

Key Applications

Automotive | Medical Device | Industrial Control | Artificial Intelligence (AI)

AMD XILINX | MYC-C7Z015

- Xilinx XC7Z015 Processor, 2x Cortex-A9@766MHz+Artix 7 FPGA
- DDR3, eMMC, QSPI Flash
- On-board Gigabit Ethernet PHY
- 75mm x 55mm; B2B Package, 2x140-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

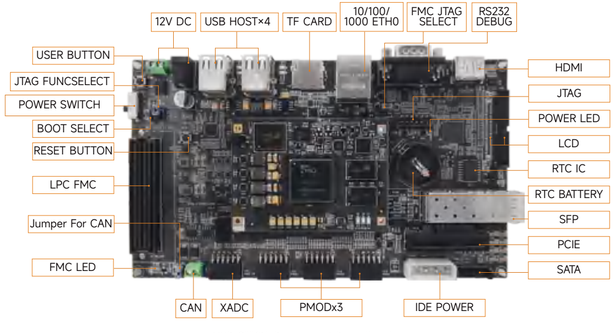
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C7Z015-4E1D-766-I	xc7z015-2clg485	2×Cortex-A9@766Hz +Atrix 7 FPGA (74K)	1GB DDR3	4GB eMMC	32MB QSPI Flash Ethernet PHY USB PHY	B2B 2×140PIN	-40°C~+85°C	75mm × 55mm	Linux	MYD-C7Z015-4E1D-766-I

Peripherals/Interfaces

Communications	RGMII, USB2.0, CAN, 2×SPI, 2×I2C, 2×XADC, SFP, PCIE, SATA
FPGA Expansion IO	137PIN (FPGA_XC7015)

Key Applications

Automotive · Medical Device · Industrial Control · Communication Systems



MYD-C7Z015 Development Board Top-view

AMD XILINX | MYC-CZU3EG/4EV/5EV-V2

- Zynq UltraScale+ ZU3EG /ZU4EV /ZU5EV MPSoC, 4x Cortex-A53@1.2GHz+2x Cortex-R5@600MHz
- DDR4, eMMC, QSPI Flash
- USB 3.0, Gigabit Ethernet, CAN, TF, DP, PCIe, SATA, HDMI, LCD
- 60mm x 52mm; B2B Package, 2x160-pin; 0°C~+70°C Commercial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

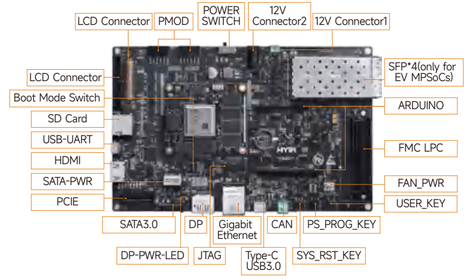
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-CZU3EG-V2-4E4D-1200-C	XCZU3EG-1SFVC784	ARM: 4×A53@1200MHz+2×R5@533MHz + UltraScale+ FPGA 154K	4GB DDR4	4GB eMMC	128MB QSPI Flash Ethernet PHY USB PHY	B2B 2×160PIN	0°C~+70°C	60mm × 52mm	Linux	MYD-CZU3EG-V2-4E4D-1200-C
MYC-CZU4EV-V2-4E4D-1200-I-FAN	XCZU4EV-2SFVC784	ARM: 4×A53@1200MHz+2×R5@533MHz + UltraScale+ FPGA 192K					-40°C~+85°C			MYD-CZU4EV-V2-4E4D-1200-C
MYC-CZU5EV-V2-4E4D-1200-I-FAN	XCZU5EV-2SFVC784	ARM: 4×A53@1200MHz+2×R5@533MHz + UltraScale+ FPGA 256K								MYD-CZU5EV-V2-4E4D-1200-C

Peripherals/Interfaces

Communications	RGMII, CAN, USB3.0, USB_UART, 2×PMOD, PCIE2.0, DP, SATA3.0, 4×SFP (Only for 4EV/5EV)
FPGA Expansion IO	156PIN (FPGA)

Key Applications

Data Center · Medical Device · Industrial Control · Automotive



MYD-CZU3EG/4EV/5EV-V2 Development Board Top-view

MYC-C335X-V4

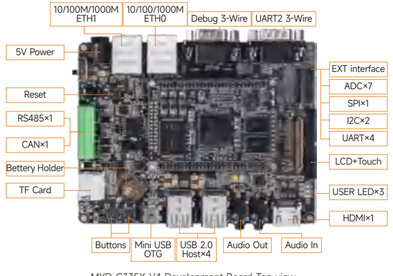
- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash, Gigabit Ethernet PHY
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN
- 70mm x 50mm; DIP Package, 2x 60-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C3352-V4-256N256D-80-I	AM3352BZCZD80	Cortex-A8@800MHz	256MB DDR3	256MB Nand FLASH	Ethernet PHY 32Kbit EEPROM	DIP 2×60PIN	-40°C~+85°C	70mm × 50mm	Linux	MYD-C3352-V4-256N256D-80-I
MYC-C3352-V4-512N512D-80-I			512MB DDR3	512MB Nand FLASH						MYD-C3352-V4-512N512D-80-I
MYC-C3352-V4-512N512D-80-C							0°C~+70°C			MYD-C3352-V4-512N512D-80-C
MYC-C3358-V4-256N256D-100-I	AM3358BZCZA100	Cortex-A8@1.0GHz	256MB DDR3	256MB Nand FLASH			-40°C~+85°C			MYD-C3358-V4-256N256D-100-I
MYC-C3358-V4-512N512D-100-I			512MB DDR3	512MB Nand FLASH						MYD-C3358-V4-512N512D-100-I
MYC-C3358-V4-512N512D-100-C							0°C~+70°C			MYD-C3358-V4-512N512D-100-C

Peripherals/Interfaces

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×McASP
Others	12bit 8ch ADC, JTAG



MYD-C335X-V4 Development Board Top-view

Key Applications

Charging PileBilling Control Unit | Medical Equipment | Industrial Control | Gaming Peripherals

MYC-Y335X-V2

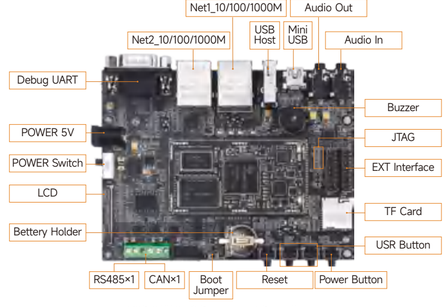
- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash, Gigabit Ethernet PHY, PMIC
- 6x UART, 2x USB 2.0, 2x Gigabit Ethernet, 2x CAN
- 65mm x 35mm; LCC Package, 146-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-Y3352-V2-256N256D-80-I	AM3352BZCZD80	Cortex-A8@800MHz	256MB DDR3	256MB Nand FLASH	Ethernet PHY 32Kbit EEPROM	LCC 146PIN	-40°C~+85°C	65mm x 35mm	Linux	MYD-Y3352-V2-256N256D-80-I
MYC-Y3358-V2-256N256D-100-I	AM3358BZCZA100	Cortex-A8@1.0GHz								MYD-Y3358-V2-256N256D-100-I

Peripherals/Interfaces

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×McASP
Others	2×12bit 8ch ADC, JTAG



MYD-Y335X-V2 Development Board Top-view

Key Applications

Charging PileBilling Control Unit | Medical Equipment | Industrial Control | Gaming Peripherals

MYC-J335X-V2

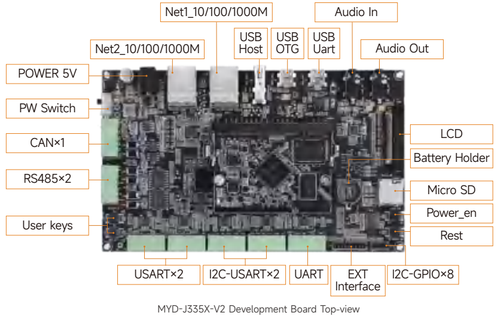
- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash, Gigabit Ethernet PHY, PMIC
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN, 2x SPI
- 67mm x 45mm; MXM Package, 200-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-J3352-V2-256N256D-80-I	AM3352BZCZD80	Cortex-A8@800MHz	256MB DDR3	256MB Nand FLASH	Ethernet PHY 32Kbit EEPROM	MXM 200PIN	-40°C~+85°C	67mm x 45mm	Linux	MYD-J3352-V2-256N256D-80-I
MYC-J3358-V2-256N256D-100-I	AM3358BZCZA100	Cortex-A8@1.0GHz								MYD-J3358-V2-256N256D-100-I

Peripherals/Interfaces

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×McASP
Others	12bit 8ch ADC, JTAG

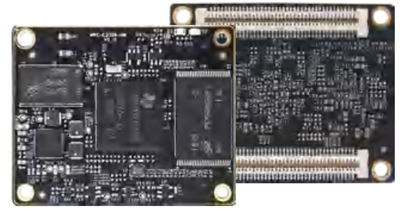


MYD-J335X-V2 Development Board Top-view

Key Applications

Charging PileBilling Control Unit | Medical Equipment | Industrial Control | Gaming Peripherals

MYC-C335X-GW



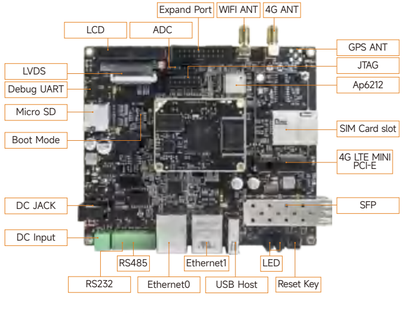
- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash/eMMC, EEPROM, PMIC
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN
- 50mm x 40mm; B2B Package, 2x 80-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C3354-256N256D-80-I-GW	AM3354BZCZD80	Cortex-A8@800MHz	256MB DDR3L	256MB Nand Flash	32Kbit EEPROM	B2B 2×80PIN	-40°C~+85°C	50mm x 40mm	Linux	MYD-C3354-256N256D-80-I-GW
MYC-C3354-4E512D-80-I-GW			512MB DDR3L	4GB eMMC						MYD-C3354-4E512D-80-I-GW

Peripherals/Interfaces

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×McASP
Others	12bit 8ch ADC, JTAG

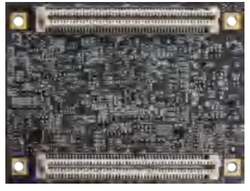


MYD-C335X-GW Development Board Top-view

Key Applications

Industrial Gateway | HMI | Medical Equipment | Industrial Control

MYC-C437X-V2



- Up to 1GHz TI AM437x Cortex-A9 Processor
- DDR3, eMMC, EEPROM, Gigabit Ethernet PHY, PMIC
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN, 2x SPI, 3x I2C, 2x Parallel Camera Interfaces
- 45mm x 60mm; B2B Package, 200-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

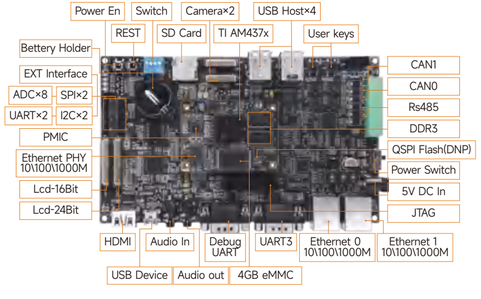
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C4378-V2-4E512D-100-C	AM4378BZDND100	Cortex-A9@1.0GHz	512MB DDR3	4GB eMMC	Ethernet PHY 32KB EEPROM	B2B 200PIN	0°C~+70°C	45mm x 60mm	Linux	MYD-C4378-V2-4E512D-100-C
MYC-C4378-V2-4E512D-100-I							-40°C~+85°C			MYD-C4378-V2-4E512D-100-I

Peripherals/Interfaces

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×Parallel CSI, 2×McASP
Others	2×12bit 8ch ADC, JTAG

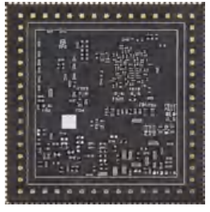
Key Applications

Industrial HMI | Medical Equipment | Industrial Control | Code Scanner



MYD-C437X-V2 Development Board Top-view

MYC-YM62X



- TI AM62x Processor, 1/2/4x Cortex-A53@1.4GHz + Cortex-M4F@400MHz
- DDR4, eMMC, EEPROM, PMIC
- 3D GPU (Only for AM625), full-HD dual-display support
- 2x Display Controllers, 2x USB2.0, 2x Gigabit Ethernet, 3x CAN-FD, 1x GPMC
- 43mm x 45mm; LCC + LGA Package, 164-pin + 58-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

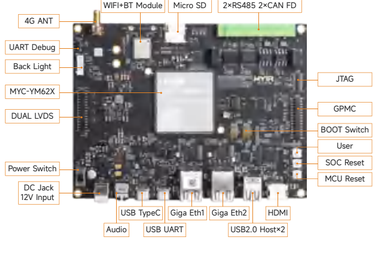
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YM6254-8E2D-140-I	AM6254ATCGGAALW	4×Cortex-A53@1.4GHz+ Cortex-M4F@400MHz	2GB DDR4	8GB eMMC	32Kbit EEPROM	LCC+LGA 222PIN	-40°C~+85°C	43mm x 45mm	Linux	MYD-YM6254-8E2D-140-I
MYC-YM6252-8E1D-140-I	AM6252ATCGGAALW	2×Cortex-A53@1.4GHz+ Cortex-M4F@400MHz	1GB DDR4							MYD-YM6252-8E1D-140-I
MYC-YM6231-8E1D-140-I	AM6231ASGGGAALW	Cortex-A53@1.0GHz+ Cortex-M4F@400MHz	1GB DDR4							MYD-YM6231-8E1D-140-I

Peripherals/Interfaces

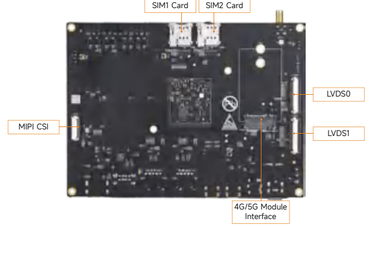
Communications	2×RGMII, 2×USB 2.0, 9×URAT, 3×CAN FD, 4×I2C, 5×SPI
Multimedia	2×LVDS, 1×RGB, 1×MIPI CSI, 3×MCASP
Others	1×GPMC, 1×JTAG

Key Applications

Industrial HMI | Medical Device | Industrial Control | Energy & Power



MYD-YM62X Development Board Top-view



MYD-YM62X Development Board Bottom-view

RENESAS | MYC-YG2UL

- RENESAS RZ/G2UL Processor, 64-bit MPU, Cortex-A55@1.0GHz + Cortex-M33@200MHz
- DDR3L, eMMC, EEPROM
- Camera Interface, Display Interface, USB2.0, CAN-FD, Dual Gigabit Ethernet
- 37mm x 39mm; LCC + LGA Package, 190-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

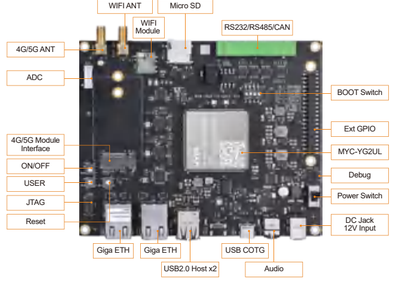
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YG2UL-4E512D-100-I	R9A07G043U11GBG	Cortex-A55@1.0GHz+ Cortex-M33@200MHz	512MB DDR3	4GB eMMC	32KBit EEPROM	LCC+LGA 190PIN	-40°C~+85°C	37mm x 39mm	Linux OpenWrt	MYD-YG2UL-4E512D-100-I

Peripherals/Interfaces

Communications	2×RGMII, 2×CAN FD, 2×USB2.0, 7×UART, 3×SPI, 4×I2C
Multimedia	RGB, MIPI CSI, 4×SSI
Others	12-bit 2-ch ADC, JTAG

Key Applications

Charging Pile | Motion Controller | Engineering Machinery | Medical Device



MYD-YG2UL Development Board Top-view

MYD-YG2UL Development Board Bottom-view

RENESAS | MYC-YG2LX

- RENESAS RZ/G2L Processor, 2x Cortex-A55@1.2GHz + Cortex-M33@200MHz
- Integrated 3D Graphics engine and video CODEC engine (H.264)
- Rich Multimedia Interfaces: MIPI-DSI / RGB / MIPI-CSI / Parallel CSI
- 43mm x 45mm; LCC + LGA Package, 222-pin; -40°C~+85°C Industrial; Linux / Ubuntu OS

Part Selections (Other Configurations can be Customized for Mass Production)

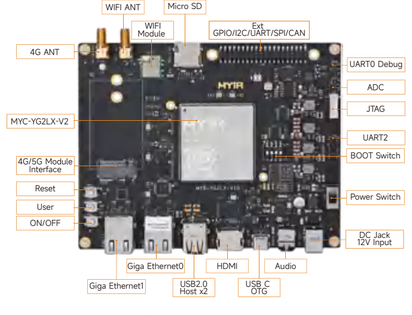
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YG2L23-8E1D-120-I	R9A07G044L23GBG	2×Cortex-A55@1.2GHz+ Cortex-M33@200MHz	1GB DDR4	8GB eMMC	32KB EEPROM	LCC+LGA 222PIN	-40°C~+85°C	43mm x 45mm	Linux Ubuntu	MYD-YG2L23-8E1D-120-I
MYC-YG2L23-8E2D-120-I			2GB DDR4							MYD-YG2L23-8E2D-120-I

Peripherals/Interfaces

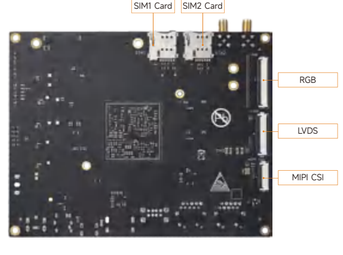
Communications	2×RGMII, 2×CAN FD, 2×USB2.0, 7×UART, 3×SPI, 4×I2C
Multimedia	RGB, MIPI DSI, Parallel CSI, MIPI CSI, SSI, SRC
Others	12-bit 8-ch ADC, JTAG

Key Applications

Industrial HMI | Industrial Gateway | Industrial Control | Energy & Power



MYD-YG2LX Development Board Top-view



MYD-YG2LX Development Board Bottom-view

MYC-YT113i

- Allwinner T113-i Processor, 2x Cortex-A7@1.2GHz + RISC-V@800MHz
- DDR3, eMMC, EEPROM
- 1x Gigabit Ethernet, 2x USB2.0, 6x UART, 2x CAN, 8x PWM, 1x GPADC, 4x TPADC
- 37mm x 39mm; LCC + LGA Package, 140-pin + 50-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

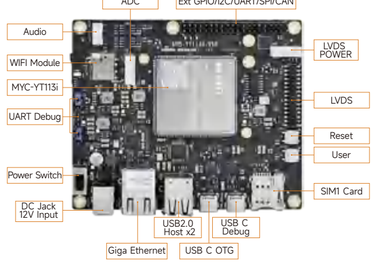
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YT113i-4E256D-110-I	T113-i	2×Cortex-A7@1.2G +RISC-V@800MHz	256MB DDR3	4GB eMMC	32Kbit EEPROM	LCC+LGA 140+50PIN	-40°C~+85°C	37mm x 39mm	Linux	MYD-YT113i-4E256D-110-I
MYC-YT113i-4E512D-110-I			512MB DDR3							MYD-YT113i-4E512D-110-I
MYC-YT113i-8E512D-110-I				8GB eMMC						MYD-YT113i-8E512D-110-I
MYC-YT113i-8E1D-110-I			1GB DDR3							MYD-YT113i-8E1D-110-I

Peripherals/Interfaces

Communications	RGMII, 2×USB2.0, 6×UART, 2×CAN, SDIO, SPI, 4×I2C, 8×PWM
Multimedia	MIPI DSI, RGB DSI, Dual link LVDS, CVBS OUT, Parallel CSI, 2×I2S

Key Applications

Commercial Display | Medical Equipment | Industrial Control | Energy & Power



MYD-YT113i Development Board Top-view

MYD-YT113i Development Board Bottom-view

MYC-YT113X

- Allwinner T113-S3 Processor, 2x Cortex-A7@1.2GHz, with built-in 128MB DDR3
- Rich multimedia interfaces: MIPI-DSI / RGB / LVDS / Parallel CSI
- 6x UART, 2x USB2.0, 1x Gigabit Ethernet, 2x CAN
- 37mm x 39mm; LCC Package, 140-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

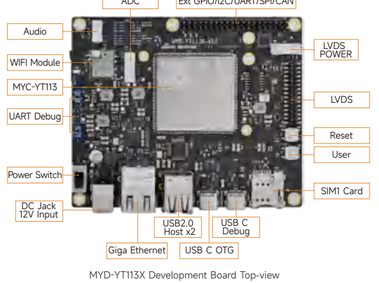
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YT113S3-256N128D-110-I	T113-S3	2×Cortex-A7@1.2GHz	128MB DDR3	256MB Nand Flash	32Kbit EEPROM	LCC 140PIN	-40°C~+85°C	37mm x 39mm	Linux	MYD-YT113S3-256N128D-110-I
MYC-YT113S3-4E128D-110-I				4GB eMMC						MYD-YT113S3-4E128D-110-I

Peripherals/Interfaces

Communications	RGMII, 2×USB2.0, 6×UART, 2×CAN, SDIO, 2×SPI, 4×I2C, 8×PWM
Multimedia	MIPI DSI, RGB DSI, 2×LVDS, Parallel CSI, 2×I2S

Key Applications

Commercial Display | Medical Equipment | Industrial Control | Energy & Power

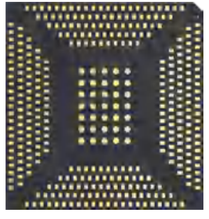


MYD-YT113X Development Board Top-view

MYD-YT113X Development Board Bottom-view

ALLWINNER | MYC-LT536

- Allwinner T536 processor, 4x Cortex-A55@1.6GHz + RISC-V@600MHz
- LPDDR4, eMMC, EEPROM, PMIC
- 2 Tops NPU (T536MX-CEN2), Graphic 2D, 4K HD Video Codec
- 43mm x 45mm; LGA Package, 381-pin; -40°C~+85°C Industrial; Linux



Part Selections (Other Configurations can be Customized for Mass Production)

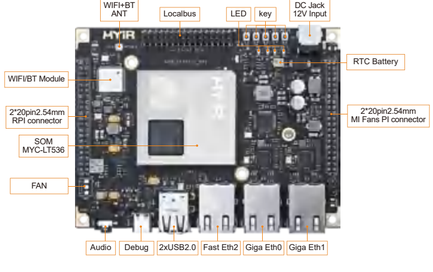
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LT536ME-8E1D-160-I	T507H	4×Cortex-A55@1.6GHz+ RISCV@600MHz	1GB LPDDR4X	8GB eMMC	32Kbit EEPROM	LGA 381PIN	-40°C~+85°C	43mm x 45mm	Linux	MYD-LT536ME-8E1D-160-I-GK
MYC-LT536ME-16E2D-160-I			2GB LPDDR4X	16GB eMMC						MYD-LT536ME-16E2D-160-I-GK
MYC-LT536MN2-32E4D-160-I	T536MX-CEX	4×Cortex-A55@1.6GHz+ RISCV@600MHz, 2Tops NPU	4GB LPDDR4X	32GB eMMC						MYD-LT536MN2-32E4D-160-I-GK

Peripherals/Interfaces

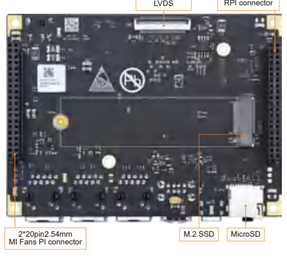
Communications	2×RGMII, USB3.1 DRD/PCIE2.0, 2×USB2.0, Localbus 4×CAN FD, 17×UART
Multimedia	LVDS, MIPI DSI, Parallel DSI, 4×I2S
Others	9×I2C, 34×PWM, 6×SPI, SDIO, 26×12bit GPADC

Key Applications

Industrial Internet Devices | All-in-One Display & Control Machine | Industrial Control | Energy & Power



MYD-LT536 Development Board Top-view



MYD-LT536 Development Board Bottom-view

ALLWINNER | MYC-YT507H

- Allwinner T507-H processor, 4x Cortex-A53@1.5GHz
- LPDDR4, eMMC, EEPROM, PMIC
- Supports 4K@60FPS H.265 video decoding and 4K@25FPS H.264 video encoding
- Supports different display in dual screens, MIPI CSI and DVP camera inputs
- 43mm x 45mm; LCC + LGA Package, 164-pin + 58-pin; -40°C~+85°C Industrial; Linux / Android / Ubuntu

Part Selections (Other Configurations can be Customized for Mass Production)

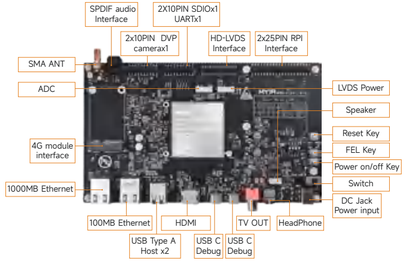
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YT507H-8E1D-150-I	T507-H	4×Cortex-A53@1.5GHz	1GB LPDDR4	8GB eMMC	32Kbit EEPROM	LCC+LGA 222PIN	-40°C~+85°C	43mm x 45mm	Linux Android Ubuntu	MYD-YT507H-8E1D-150-I
MYC-YT507H-8E2D-150-I			2GB LPDDR4							MYD-YT507H-8E2D-150-I

Peripherals/Interfaces

Communications	RGMII, 4×USB2.0, 6×UART, 2×SDIO, 2×SPI, 4×I2C, 6×PWM, 5×ADC
Multimedia	HDMI, 2×LVDS, RGB24, TV CVBS, Parallel CSI, MIPI CSI, 3×I2S, SPDIF

Key Applications

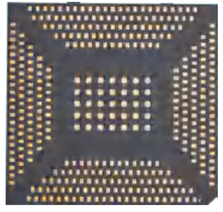
Commercial Display | Medical Equipment | Industrial Control | Intelligent Terminal



MYD-YT507H Development Board Top-view

MYD-YT507H Development Board Bottom-view

ALLWINNER | MYC-LT527



- Allwinner T527 processor, 4x Cortex-A55@1.8GHz + 4x Cortex-A55@1.4GHz + RISC-V@200MHz
- Up to 2 Tops NPU, LPDDR4, eMMC, EEPROM, PMIC
- G57 GPU, 4K encoding/decoding VPU, HiFi4 DSP, 4 to 6 camera inputs
- Multi video output interfaces: HDMI, DP, LVDS, MIPI-DSI, and RGB; Supports 4K+1080P dual-screen display
- 43mm x 45mm; LGA Package, 381-pin; -40°C~+85°C Industrial; Linux / Android / Ubuntu

Part Selections (Other Configurations can be Customized for Mass Production)

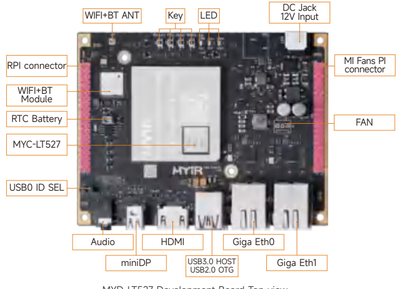
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC- LT527MN-16E2D-180-I-G	T527MN	4×Cortex-A55@1.8GHz +4×Cortex-A55@1.4GHz, RISC-V@200MHz, HIFI4 600MHz, 2Tops NPU	2GB LPDDR4	16GB eMMC	32Kbit EEPROM	LGA 381PIN	-40°C~+85°C	43mm x 45mm	Linux Android Ubuntu	MYD- LT527MN-16E2D-180-I
MYC- LT527MN-32E4D-180-I-G			4GB LPDDR4	32GB eMMC						MYD- LT527MN-32E4D-180-I
MYC- LT527M-16E2D-180-I-G	T527M	4×Cortex-A55@1.8GHz +4×Cortex-A55@1.4GHz, RISC-V@200MHz	2GB LPDDR4	16GB eMMC			-40°C~+85°C			MYD- LT527M-16E2D-180-I
MYC- LT527M-16E2D-180-E							-20°C~+70°C			MYD- LT527M-16E2D-180-E

Peripherals/Interfaces

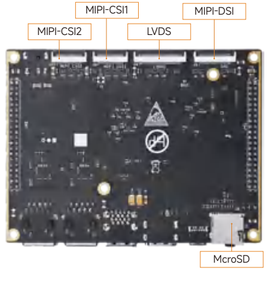
Communications	RGMII, 4×USB2.0, 6×UART, 2×SDIO, 2×SPI, 4×I2C, 6×PWM, 5×ADC
Multimedia	HDMI, 2×LVDS, RGB24, TV CVBS, Parallel CSI, MIPI CSI, 3×I2S, SPDIF

Key Applications

Commercial Display | Medical Equipment | Industrial Control | Intelligent Terminal



MYD-LT527 Development Board Top-view



MYD-LT527 Development Board Bottom-view

芯驰 SemiDrive | MYC-JD9360

- SemiDrive D9-Pro processor, 6x Cortex-A55@1.6GHz + Cortex-R5@800MHz + 0.8 Tops NPU
- Support dual display at 1080p resolution of different contents
- Support the third HMI display through Cortex-R5 co-processor control
- HD vision processing unit (VPU): H.264 encoding and decoding 4Kp30, H.265 decoding 4Kp30
- 82mm x 45mm; MXM Package, 314-pin; -40°C~+85°C Industrial; Linux / Ubuntu

Part Selections (Other Configurations can be Customized for Mass Production)

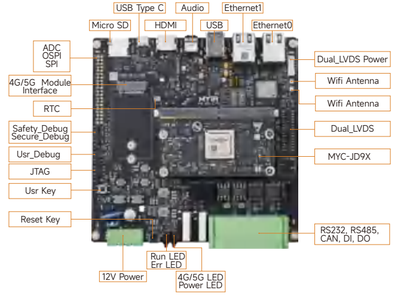
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-JD9360-16E2D-160-I	D9-Pro	6×Cortex-A55@1.6GHz +Cortex-R5@800MHz +0.8Tops NPU	2GB LPDDR4	16GB eMMC	EEPROM	MXM 314PIN	-40°C~+85°C	82mm × 45mm	Linux Ubuntu	MYD-JD9360-16E2D-160-I

Peripherals/Interfaces

Communications	2×RGMII, 2×USB3.0, 2×PCIe3.0, 16×UART, 4×CAN FD, 2×SDIO, 8×SPI, 12×I2C, 8×PWM, 4×ADC
Multimedia	MIPI DSI, LVDS, MIPI CSI, Parallel CSI

Key Applications

Construction Machinery T-BOX | Intelligent Medical Equipment | Industrial Robot | Smart Cockpit

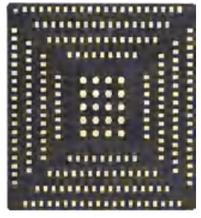


MYD-JD9360 Development Board Top-view

MYD-JD9360 Development Board Bottom-view

nuvoTon | MYC-LMA35

- Nuvoton NuMicro MA35D1 with Stacked 256MB DDR3L, 2x Cortex-A35@800MHz + Cortex-M4@180MHz
- Nand Flash / eMMC, EEPROM
- 4x CAN FD, 17x UART, 2x I2S, 6x I2C, 8x EADC, 1x JTAG, 1x RGB, 2x Parallel CSI, 18x EPWM, 4x SPI
- 2D Graphic Engine (GFX), LCD display controller with the resolution up to 1080p@60 FPS
- 37mm x 39mm; LGA Package, 252-pin; -40°C~+85°C Industrial; Linux / Debian



Part Selections (Other Configurations can be Customized for Mass Production)

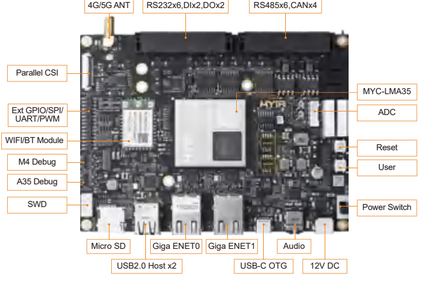
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LMA35-256N256D-80-I	MA35D16A887C	2x Cortex-A35@800MHz +Cortex-M4@180MHz	256MB DDR3L	256MB Nand Flash	32KBit EEPROM	LGA 252PIN	-40°C~+85°C	37mm × 39mm	Linux Debian	MYD-LMA35-256N256D-80-I
MYC-LMA35-8E256D-80-I				8GB eMMC						MYD-LMA35-8E256D-80-I
MYC-LMA35-8E512D-80-I	MA35D16AJ87C		512MB DDR3L							MYD-LMA35-8E512D-80-I

Peripherals/Interfaces

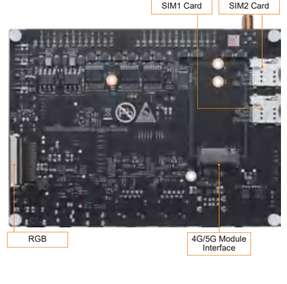
Communications	2×RGMII, 2×USB 2.0, 4×CAN FD, 17×UART, 4×SPI, 6×I2C, SDIO 3.0
Multimedia	1×RGB, 2×Parallel CSI, 2×I2S
Others	8×EADC, 1×JTAG, 18×EPWM

Key Applications

Industrial Gateway | Charging Pile | Industrial Manufacturing | Electricity DTU



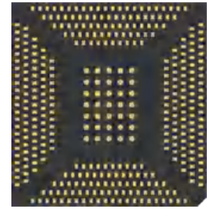
MYD-LMA35 Development Board Top-view



MYD-LMA35 Development Board Bottom-view

Rockchip | MYC-LR3568

- Rockchip RK3568 processor, 4x Cortex-A55@up to 2.0GHz + 1 Tops NPU
- LPDDR4, eMMC, EEPROM
- Supports 4K 60fps H.265/H.264/VP9 Decoder and 1080P 60fps H.265/H.264 Encoder
- Arm Mali-G52 2EE GPU with support for OpenGL ES 1.1/2.0/3.2, OpenCL 2.0, Vulkan 1.1
- 43mm x 45mm; LGA Package, 381-pin; -40°C~+85°C Industrial or -20°C~+70°C Extended; Linux / Debian



Part Selections (Other Configurations can be Customized for Mass Production)

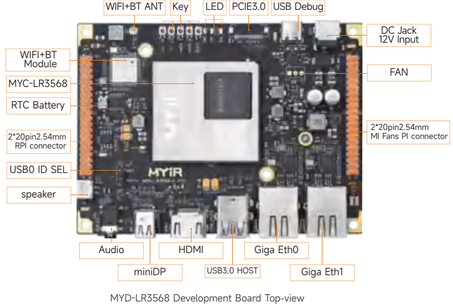
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LR3568J-16E2D-180-I	RK3568J	4×Cortex-A55@1.4GHz	2GB DDR4	16GB eMMC	32KB EEPROM	LGA 381PIN	-40°C~+85°C	43mm × 45mm	Linux Debain	MYD-LR3568J-16E2D-180-I-GK
MYC-LR3568B2-16E2D-200-E	RK3568B2	4×Cortex-A55@2.0GHz					-20°C~+70°C			MYD-LR3568B2-16E2D-200-E

Peripherals/Interfaces

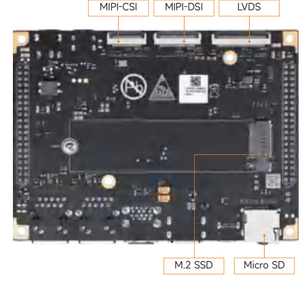
Communications	2×RGMII, 2×USB2.0, 2×USB3.0, 2×PCIe3.0, PCIe2.1, SDIO SATA3.0, 10×UART, 3×CAN, 4×SPI, 6×I2C, 16×PWM, 8×ADC
Multimedia	HDMI2.0a, eDP1.3, Dual MIPI-DSI_TX, Single LVDS, Parallel DSI 2×MIPI CSI, Parallel CSI, 4×I2S/TDM, 8×ADC

Key Applications

Industrial HMI | Charging Pile | Industrial Manufacturing | Energy & Power



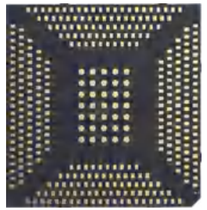
MYD-LR3568 Development Board Top-view



MYD-LR3568 Development Board Bottom-view

Rockchip | MYC-LR3576

- Rockchip RK3576 processor, 4x Cortex-A72@2.2GHz + 4x Cortex-A53@1.8GHz + Cortex-M0@400MHz
- LPDDR4X, eMMC, EEPROM
- Neural Processing Unit (NPU) Operating at Up to 6 TOPS, 3D GPU
- Supports Up to 4K@120fps High Frame Rate Video Decoding
- 43mm x 45mm; LGA Package, 381-pin; 0°C~+70°C Commercial or -40°C~+85°C Industrial; Linux / Debian



Part Selections (Other Configurations can be Customized for Mass Production)

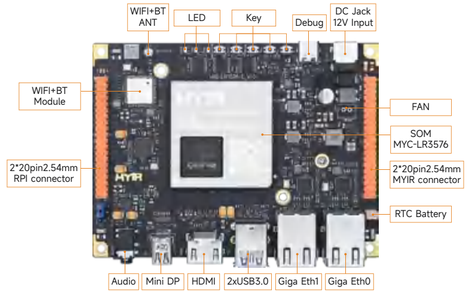
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LR3576-32E4D-220-C	RK3576	4×Cortex-A72@2.2GHz + 4×Cortex-A53@1.8GHz + Cortex-M0@400MHz 6TOPS NPU	4GB LPDDR4X	32GB eMMC	32Kbit EEPROM	LGA 381PIN	0°C~+70°C	43mm × 45mm	Linux Debain	MYD-LR3576-32E4D-220-C
MYC-LR3576-64E8D-220-C			8GB LPDDR4X	64GB eMMC						MYD-LR3576-64E8D-220-C
MYC-LR3576J-32E4D-160-I	RK3576J	4×Cortex-A72@2.1GHz + 4×Cortex-A53@1.9GHz + Cortex-M0@400MHz 6TOPS NPU	4GB LPDDR4X	32GB eMMC			-40°C~+85°C			MYD-LR3576J-32E4D-160-I-GK
MYC-LR3576J-64E8D-160-I			8GB LPDDR4X	64GB eMMC						MYD-LR3576J-64E8D-160-I-GK

Peripherals/Interfaces

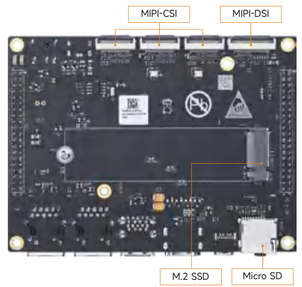
Communications	2×RGMII, USB/DP combo, PCIe2.1, SDIO, SATA3.0, 12×UART, 2×CAN FD, 5×SPI, 10×I2C, 10×I3C, DSMC/FlexBus
Multimedia	2×MIPI-CSI, DVP, HDMI, MIPI-DSI, 2×SPDIF TX, 2×SPDIF RX, 5×I2S
Others	8×SARADC

Key Applications

Intelligent Healthcare | Automotive Electronics | Industrial Manufacturing | Energy & Power



MYD-LR3576 Development Board Top-view



MYD-LR3576 Development Board Bottom-view

Solutions and Applications

Single Board Computers

The embedded industrial single board computer is a complete computing system that integrates a processor, memory, storage, and various peripheral interfaces. It has gone through rigorous design and testing, exhibiting high stability and reliability, and can operate stably for long periods in harsh industrial environments. Engineers and developers can directly carry out application development and deployment on it, and it is widely used in fields such as industrial control, industrial automation, industrial data collection, medical equipment, and more.

Single Board Computers

ARM Cores \ CPU Vendor	Allwinner	Renesas	NXP	Texas Instruments	AMD XILINX	
A7 Single-core			MYS-6ULX P55 NXP i.MX6UL/i.MX6ULL A7@528MHz 10/100M ETH, USB2.0 HOST, USB2.0 OTG, LCD Module, Micro SD Card Slot			
A9 Single or Dual-core				Rico Board P57 TI AM437X A9@1.0GHz 1000M ETH, USB2.0 Host, Mini USB2.0, HDMI, LCD Module, Dual-Camera	Z-turn Board V2 P58 AMD-Xilinx XC7Z010/20 ARM: 2×A9@667MHz/766MHz FPGA: 28K/ 85K 1000M ETH, Mini USB2.0 OTG, CAN, UART, HDMI, TF Card	Z-turn Lite P59 AMD-Xilinx XC7Z010 ARM: 2×A9@667MHz FPGA: 28K 1000M ETH, Mini USB2.0 OTG, Debug UART, JTAG, TF Card
A53 Quad-core			MYS-8MMX-V2 P56 NXP i.MX 8M Mini 4×A53@1.8GHz+M4@400MHz 1000M ETH, 2x USB2.0 HOST, USB2.0 OTG, MIPI CSI, LVDS, HDMI, M.2 PCIe		FZ3 Card P60 Xilinx XCZU3EG ARM:4xA53@1.2GHz+2xR5@600MHz FPGA: 154K 1000M ETH, USB2.0, USB3.0 Host, TF, DP, PCIe, MIPI CSI, UART, JTAG	FZ5 Card P61 Xilinx XCZU5EV ARM:4xA53@1.2GHz+2xR5@600MHz FPGA: 256K 1000M ETH, 4xUSB3.0, RS232, RS485, CAN, TF, DP, HDMI, JTAG
A55 Dual or Octa-core	MYD-LT527-SX P53 Allwinner T527 8×A55@1.8GHz 2x1000M ETH, 6×USB, 2×CAN, HDMI, MIPI DSI/CSI, WiFi/BT	Remi Pi P54 Renesas RZ/G2L 2×A55@1.2GHz+M33@200MHz 2x1000M ETH, 3xUSB2.0, WiFi/BT, MIPI CSI, LVDS, HDMI				

ALLWINNER | MYD-LT527-SX

- Allwinner T527 Processor, Up to 1.8GHz Octa-core ARM Cortex-A55 MPU with GPU
- 2GB LPDDR4, 16GB eMMC, 32Kbit EEPROM
- 2x RS232, RS485, USB 3.0, 5x USB 2.0, 2x CAN, TF Card Slot
- 2x Gigabit Ethernet, WiFi/Bluetooth, PCIe Slot for 4G/5G Module
- 2x MIPI-CSI, HDMI/Mini-DP/MIPI-DSI/LVDS, Audio Input/Output
- Supports for Android OS

MYD-LT527-SX Top-view

MYD-LT527-SX Bottom-view

Features	Description
CPU	Allwinner T527 Processor, Up to 1.8GHz 8x Cortex-A55 MPU with GPU
RAM	2GB LPDDR4
ROM	16GB eMMC
Communications	1x Debug UART (TTL)
	1x RS485
	2x RS232
	2x TTL
	2x 10/100/1000M Ethernet
	1x USB2.0 Host (Type-A)
	1x USB3.0 Host (Type-A)
	4x USB2.0 Host (4-pin header connectors)
	1x Mini PCIe Interface for USB based 4G/5G Module
	1x SIM Card Slot
	1x Micro SD card slot
	2x CAN
	1x WiFi/BT Module
	1x IR RX Jack
Multimedia	1x HDMI Display Interface
	1x Dual-LVDS Display Interface
	1x eDP Display Interface
	1x MIPI-DSI Display Interface
	2x MIPI-CSI Camera Interface
	1x 3.5mm Headphone Jack
	1x MIC Interface
	1x Stereo Speaker Interface

Key Applications

Medical Device | Energy & Power | Vehicle Terminals | Edge Intelligent Boxes

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYD-LT527M-16E2D-180-E-SX	T527M	4xCortex-A55@1.8GHz + 4×Cortex-A55@1.4GHz RISC-V@200MHz	2GB LPDDR4	16GB eMMC	-20°C~+70°C	140mm x 100mm	Android

RENESAS | Remi Pi

- RENESAS RZ/G2L Processor, 2x Cortex-A55@1.2GHz + Cortex-M33@200MHz
- 1GB DDR4, 8GB eMMC Flash, 32KB EEPROM
- 2x USB 2.0 HOST, 1x USB 2.0 OTG, 2x Gigabit Ethernet, WiFi/Bluetooth
- Camera Interface (MIPI-CSI), LVDS, HDMI, Audio Input/Output
- Optional 7-inch LCD Modules, Camera Module and RPI Module (RS232/RS485/CAN)
- Linux OS (Yocto based with QT / Debian / Ubuntu)

Remi Pi Top-view

Remi Pi Bottom-view

Features	Description
CPU	RENESAS RZ/G2L Processor, 2x Cortex-A55@1.2GHz + Cortex-M33@200MHz
RAM	1GB DDR4
ROM	8GB eMMC
Power Management	PMIC, RAA215300
Power Supply	USB Power Supply (Type-C)
WiFi/Bluetooth	2.4GHz/5GHz WIFI + BT4.2 Module
Ethernet	2x Gigabit Ethernet Interfaces
USB	1x USB 2.0 OTG (Type-C)
	2x USB 2.0 Host (Type-A)
Multimedia	1x HDMI Display Interface
	1x LVDS Display Interface
	1x MIPI-CSI Camera Interface
	1x Audio Input/Output Interface
Debug	2x Debug UART (Cortex-A55, Cortex-M33)
Buttons	ON/OFF, RESET, USER
Status LED	Power, System Status
RPI Interface	1x 2.54mm 2x 20-pin male expansion header (GPIO/I2C/UART/SPI/CAN)
RTC	Used for timing when power off

Key Applications

Industrial HMI | Medical Device | Industrial Control | Commercial Display

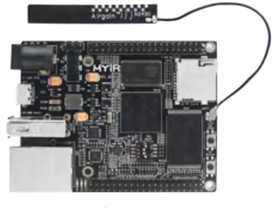
Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYD-YG2L23-8E1D-120-C-REMI	R9A07G044L23GBG	2×Cortex-A55@1.2GHz+ Cortex-M33@200MHz	1GB DDR4	8GB eMMC	0°C~+70°C	120mm x 70mm	Linux Ubuntu Debian

NXP | MYS-6ULX

- NXP i.MX 6UL/i.MX 6ULL Processor, Cortex-A7@528MHz
- 256MB DDR3, 256MB Nand Flash
- 1x USB 2.0 HOST, 1x USB 2.0 OTG, 1x 10/100Mbps Ethernet
- Optional Expansion Board adds Ethernet, CAN, RS485, Audio, RTC and Camera
- Optional 4.3 or 7 inch LCD Module, Camera and WiFi Modules
- Linux OS (Yocto based with QT / Debian)

MYS-6ULX-IND



MYS-6ULX-IOT

Features	MYS-6ULX-IND	MYS-6ULX-IOT
Target Applications	Industry 4.0	IoT Applications
CPU	MCIMX6G2CVM05AA	MCIMX6Y2DVM05AA
RAM	256MB DDR3	
ROM	256MB Nand Flash	
USB	1x USB 2.0 OTG, 1x USB 2.0 Host	
Ethernet	1x 10/100M Ethernet Interface	
TF Card	1x Micro SD Card Slot	
Key	2x Keys	
Status LED	2x User LED	
Expansion Header	2x 2.0mm pitch 2x 20-pin Male Headers (1 x Ethernet, 8 x UARTs, 4 x I2C, 2 x CAN, 4 x SPI, 8 x ADC, 4 x PWM, 2 x I2S, 1 x 8-bit Camera, 1 x JTAG, up to 46 x GPIOs)	
LCD	24-bit RGB LCD & Touch Screen (50-pin FPC connector)	
WIFI	-	1x 2.4GHz, IEEE 802.11b/g/n Standards
Working Temp.	-40°C~85°C	0°C~70°C
OS	Linux (Yocto, Debian)	Linux (Yocto, Debian)

Key Applications

Industrial HMI | Medical Device | Industrial Control | Energy & Power

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYS-6ULX-IND	MCIMX6G2CVM05AB	Cortex-A7@528MHz	256MB DDR3	256MB Nand FLASH	-40°C~+85°C	70mm x 55mm	Linux
MYS-6ULX-IOT	MCIMX6Y2CVM05AB				0°C~+70°C		

NXP | MYS-8MMX-V2

- NXP i.MX 8M Mini Processor, up to 4x Cortex-A53@1.8GHz + Cortex-M4@400MHz
- 2GB DDR4, 8GB eMMC Flash, 32MB QSPI FLASH
- 2x USB2.0 HOST, 1x USB2.0 OTG, Gigabit Ethernet, WiFi/Bluetooth, M.2 PCIe Interface
- Camera Interface (MIPI-CSI), LVDS, HDMI
- Supports Running Yocto Linux and Ubuntu OS

MYS-8MMX-V2 Top-view

MYS-8MMX-V2 Bottom-view

Features	Description
CPU	NXP i.MX 8M Mini, up to 4x Cortex-A53@1.8GHz + Cortex-M4@400MHz
RAM	2GB DDR4
ROM	8GB eMMC
Power Input	2 PIN Phoenix Connector
USB	1x USB 2.0 OTG (Type-C)
	2x USB 2.0 Host (Type-A)
Multimedia	1x HDMI Display Interface
	1x LVDS Display Interface
	1x MIPI-CSI Camera Interface
Ethernet	1x Gigabit Ethernet Interface
WiFi/Bluetooth	1x WIFI/BT Antenna SMA
RTC	1x 2PIN 1.25mm Pitch Connector
M.2	1x NVMe PCIe M.2 2242 SSD Slot
Expansion Interface	1x 2x25PIN 2.0mm Pitch Expansion Interface
Micro SD	1x Micro SD Card Slot
Debug	1x Debug UART, 3PIN 2.54mm Pitch
Buttons	ON/OFF, RESET, USER
Status LED	User, System Status

Key Applications

Medical Device | Energy & Power | Industrial Control | Intelligent Fire Systems

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software	Enclosure
MYS-8MMQ6-V2-8E2D-180-C	MIMX8MM6DVTLZAA	4×Cortex-A53@1.8GHz+ Cortex-M4@400MHz	2GB DDR4	8GB eMMC	0°C~+70°C	95mm x 69mm	Linux Ubuntu	Without
MYS-8MMQ6-V2-8E2D-180-C-B						135mm x 74.5mm x 35.8mm		With
MYS-8MMQ6-V2-8E2D-160-I	MIMX8MM6CVTKZAA	4×Cortex-A53@1.6GHz+ Cortex-M4@400MHz			-40°C~+85°C	95mm x 69mm		Without
MYS-8MMQ6-V2-8E2D-160-I-B						135mm x 74.5mm x 35.8mm		With

Texas Instruments | Rico Board

- Up to 1GHz TI AM437x Sitara ARM Cortex-A9 Processor
- 512MB DDR3 SDRAM, 4GB eMMC Flash, 16MB QSPI Flash, 32KB EEPROM
- UARTs, USB Host/Device, Gigabit Ethernet, Dual-Camera, TF, ...
- Supports HDMI and LCD Display
- Supports for Linux OS

Features	Description
CPU	Up to 1GHz TI AM437x Sitara ARM Cortex-A9 Processor
RAM	512MB DDR3
ROM	4GB eMMC, 16MB QSPI Flash, 32KB EEPROM
Display	24-bit true color display interface
USB	1x USB 2.0 Host port, 1x Mini USB 2.0 Device port
HDMI	1x HDMI Display interface
TF Card	1x TF card interface
Camera	2x Camera interfaces
Ethernet	1x Gigabit Ethernet Interface
UART	1x Debug UART
JTAG	1x 20-pin JTAG interface
Expansion Interface	2x SPI, 2x I2C, 2x CAN, 4x UARTs, 1x MMC, 8x ADC
PCB	8-layer design
Dimensions	65mm x 100mm
OS Support	Linux

Rico Board Top-view

Rico Board Bottom-view

Key Applications

Industrial HMI | Medical Device | Industrial Control | Scanner

Part Selections (Other Configurations can be Customized for Mass Production)

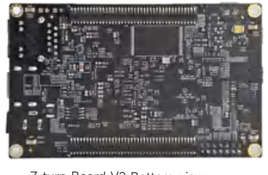
Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software	Accessories
MYS-4378-100-C	AM4378BZDN100	Cortex-A9@1.0GHz	512MB DDR3	4GB eMMC	0°C~+70°C	100mm x 65mm	Linux	With
MYS-4378-100-C-S								Without

AMD XILINX | Z-turn Board V2

- Xilinx XC7Z010/20 Processor, 2*Cortex-A9@667MHz+Artix 7 FPGA
- 1GB DDR3, 16MB QSPI Flash, 64Kbit EEPROM
- USB_UART, USB2.0 OTG, 1 x 10/100/1000Mbps Ethernet, CAN, HDMI, TF, ...
- Onboard Three-axis Acceleration Sensor and Temperature Sensor
- Supports Optional Camera Module and Z-turn IO Cape
- Ready-to-Run Linux Single Board Computer
- Supports Python Development

Features	Description
CPU	Xilinx XC7Z010/XCZ7020
RAM	1GB DDR3 SDRAM
ROM	16MB QSPI Flash
Sensor	Onboard Three-axis Acceleration Sensor, Temperature Sensor
USB	1x Mini USB2.0 OTG, 1 x USB-UART debug interface
HDMI	1x HDMI (supports 1080p resolution)
TF	1x TF card interface
CAN	1x CAN
Ethernet	1x 10/100/1000Mbps Ethernet Interface
User I/O	2x 1.27mm pitch 80-pin SMT female connectors
	PLIO: 90/106 (XC7Z010/XC7Z020)
Dimensions	63mm x 102mm x 1.6mm (8-layer PCB design)
OS support	Linux

Z-turn Board V2 Top-view



Z-turn Board V2 Bottom-view

Key Applications

Automotive | Medical Device | Industrial | Visual Monitoring

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software	Accessories
MYS-7Z010-V2-0E1D-667-C	XC7Z010-1CLG400	2×Cortex-A9@667Hz +Atrix 7 FPGA (28K)	1GB DDR3	16MB QSPI Flash	0°C~+70°C	63mm × 102mm	Linux	With
MYS-7Z010-V2-0E1D-667-C-S								Without
MYS-7Z020-V2-0E1D-766-C	XC7Z020-2CLG400	2×Cortex-A9@766Hz +Atrix 7 FPGA (85K)						With
MYS-7Z020-V2-0E1D-766-C-S								Without

AMD XILINX | Z-turn Lite

- Xilinx XC7Z010 Processor, 2*Cortex-A9@667MHz+Artix 7 FPGA
- 512MB DDR3, 4GB eMMC, 16MB QSPI Flash
- USB2.0 OTG, 10/100/1000M Ethernet, TF, Debug UART, JTAG…
- One 120 Position Connector Socket for Expansion interface
- Ready-to-Run Linux Single Board Computer
- Optional Camera and LCD Modules, IO Extension Cape

Z-turn Lite Top-view

Z-turn Lite Bottom-view

Features	Description
CPU	Xilinx XC7Z010
RAM	512MB DDR3 SDRAM
ROM	4GB eMMC Flash, 16MB QSPI Flash
Ethernet	1x 10/100/1000Mbps Ethernet Interface
USB	1x Mini USB2.0 OTG
Input and Output	1x 2.54mm pitch 14-pin JTAG Interface
	1x 0.5mm pitch 120 Position Connector Socket for Expansion Interface
	1x 2.54mm pitch 4-pin Debug UART Interface
TF	1x TF card interface
Buttons	1x Reset, 1 x User
Dimensions	91mm x 63mm (10-layer PCB design)
OS support	Linux

Key Applications

Automotive | Medical Device | Industrial | Visual Monitoring

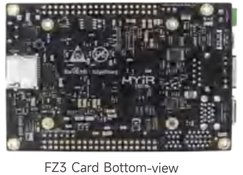
Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Other Storage	Working Temp	Dimensions	Software	Accessories
MYS-7Z010-L-C	XC7Z010-1CLG400	2×Cortex-A9@667Hz +Atrix 7 FPGA （28K）	512MB DDR3	4GB eMMC	16MB QSPI Flash	0℃~+70℃	91mm x 63mm	Linux	With
MYS-7Z010-L-C-S									Without

AMD XILINX | FZ3 Card

- Xilinx Zynq UltraScale+ ZU3EG MPSoC Processor, 4*Cortex-A53@1.2GHz+2*Cortex-R5@600MHz
- DDR4, eMMC, QSPI Flash, EEPROM
- USB2.0, USB3.0, Gigabit Ethernet, TF, DP, PCIe, MIPI-CSI, BT1120, USB-UART, JTAG…
- Computing Power up to 1.2TOPS, MobileNet up to 100FPS
- Ready-to-Run PetaLinux 2020.1
- Supports Xilinx Vitis Software Development Platform

FZ3 Card Top-view



FZ3 Card Bottom-view

Features	Description
CPU	XCZU3EG
RAM	4GB DDR4 (64-bit)
ROM	8GB eMMC
QSPI FLASH	32MB QSPI
EEPROM	32KB I2C EEPROM
PHY	1x Gigabit PHY
	2x USB 2.0 PHY
Mini DP	4K/30fps (2lane)
Ethernet	1x Gigabit Ethernet Interface
USB	1x USB 2.0 Host, 1x USB 3.0 Host
PCIe	PCIe 2.1 x 1 lane
MIPI	FPC_25PIN 4lane
BT1120	FPC_32PIN 16bit
Debug	1x Mini USB-to-UART Port
Expansion IOs	2x 2.54mm pitch 2 x 20-pin IO Expansion Interfaces
PCB	12-layer Design
Dimensions	100mm x 70mm

Key Applications

Security Monitoring | Industrial Quality Assurance | Medical Device | Artificial Intelligence (AI)

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Other Storage	Software	Accessories
MYS-ZU3EG-8E4D-EDGE-K2	XCZU3EG-1SFVC784I	ARM: 4×A53@1200MHz+ 2×R5@533MHz+ UltraScale+ FPGA 154K	4GB DDR4	8GB eMMC	-40℃~+85℃	32MB QSPI FLASH 32Kbit EEPROM	Linux	With

FZ5 Card

- Zynq UltraScale+ XCZU5EV MPSoC, 4x Cortex-A53@1.2GHz + 2x Cortex-R5@600MHz+FPGA
- Computing Power up to 2.4TOPS, Runs at 55 FPS for ResNet-50
- 8GB DDR4, 32GB eMMC, 64MB QSPI Flash, 32KB EEPROM
- RS232, RS485, 4 x USB 3.0, Gigabit Ethernet, CAN, TF, DP, HDMI-IN, JTAG…
- Supports 8- to 16-channel Video Decoding and 4- to 8-channel Intelligent Analysis
- Ready-to-Run PetaLinux

FZ5 Card Top-view

FZ5 Card Bottom-view

Features	Description
CPU	XCZU5EV
RAM	8GB DDR4 (64bit, 2400MHz)
ROM	32GB eMMC
QSPI FLASH	64MB QSPI
EEPROM	32KB EEPROM
Serial Ports	1x RS232, 1x RS485, 1 x USB-UART Debug
Ethernet	1x Gigabit Ethernet
USB3.0	4x USB3.0 Host
CAN	1x CAN
HDMI	1x HDMI In
MIPI DP	1x Mini DisplayPort (DP), 4K/30fps
User I/O	1x FPC_40PIN (Reserved for MIPI-CSI)
	1x 1.27mm pitch 2 x 50-pin IO Expansion Interface (5 x PS_MIO, 69 x PL_IO)

Key Applications

Intelligent Security | Medical Diagnosis | Artificial Intelligence (AI) | Consumer Electronics

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Other Storage	Software
MYS-ZU5EV-32E8D-EDGE-BOX	XCZU5EV-2SFVC784I	4x Cortex-A53@1.5GHz+ 2x Cortex-R5@600MHz	8GB DDR4	32GB eMMC	-40°C~+70°C	32KB EEPROM	PetaLinux

Solutions and Applications

Industrial Personal Computers (IPCs)

The Industrial Personal Computer (IPC) is an embedded computer specially designed for industrial control applications. It adopts an integrated design, integrating the single board computer, communication module, components, and housing into a single device. The entire unit features anti-interference, resistance to high and low temperature, dustproof and waterproof, and long time and stable operation, etc. It is widely used in industrial automation, instrumentation testing, data acquisition, the Internet of Things, intelligent transportation, energy management, medical equipment, rail transportation, and other fields.

Rockchip | MYD-LR3568-GK-B

- Rockchip RK3568 Application Processor based on Up to 1.8GHz Quad ARM Cortex-A55 Cores
- LPDDR4, eMMC, EEPROM
- 2x USB 3.0, 3x USB 2.0, 2x CAN, RS232, 2x RS485, Debug (USB-UART), Micro SD Card Slot
- 2x Gigabit Ethernet, WiFi/Bluetooth, PCIe Slot for 4G Module
- Supports Mini-DP and HDMI for High-resolution Displays, along with Audio Input/Output Interface
- Supports Linux and Debian OS

MYD-LR3568-GK-B Front-view

MYD-LR3568-GK-B Back-view

Features	Description
CPU	Rockchip RK3568 Processor, Up to 1.8GHz Quad ARM Cortex-A55 Cores
RAM	2GB/4GB LPDDR4
ROM	16GB/32GB eMMC
EEPROM	32KB EEPROM
Communications	1x USB-UART Debug Interface
	1x RS232
	2x RS485
	2x USB 3.0 Host Ports
	3x USB 2.0 Host Ports
	2x 10/100/1000Mbps Ethernet Interfaces
	2x CAN
	WiFi/Bluetooth Module
	1x WiFi/BT antenna interface
	1x M.2 Socket for a USB-based 4G LTE Module
	1x SIM card holder
Multimedia	1x HDMI 2.0 Interface
	1x Mini DisplayPort (DP) Output Interface
	1x 3.5mm Headphone/Mic Audio Jack

Key Applications

Industrial Personal Computer

Multi-screen HD Player

Power Measurement & Control Terminal

Data Acquisition

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYD-LR3568J-16E2D-180-I-GK-B	RK3568J	4xCortex-A55@Up to 1.8GHz	2GB LPDDR4	16GB eMMC	-40°C~+85°C	160mm x 93.5mm x 44mm (with mounting bracket)	Linux Debian
MYD-LR3568J-32E4D-180-I-GK-B			4GB LPDDR4	32GB eMMC			

NXP | MYS-8MMX-V2 Box

- NXP i.MX 8M Mini Processor, up to 1.8 GHz Arm Cortex-A53 and 400MHz Cortex-M4 Cores
- 2GB DDR4, 8GB eMMC Flash, 32MB QSPI Flash
- 2x USB Host, 1x USB Type-C, 1x Gigabit Ethernet, WiFi/Bluetooth, Micro SD Card Slot, HDMI
- Supports Running Yocto Linux and Ubuntu OS

MYS-8MMX-V2 Box Front-view

MYS-8MMX-V2 Box Back-view

Features	Description
CPU	NXP i.MX 8M Mini, up to 4x Cortex-A53@1.8GHz + Cortex-M4@400MHz
RAM	2GB DDR4 (supports up to 4GB)
Storage	8GB eMMC (supports up to 128GB)
	32MB QSPI Flash
	1x Micro SD card slot
Power Supply	5V/2A (Power Input Interface: 2-pin phoenix connector)
Dimensions	135mm (L, including ears) x 74.5mm (W) x 35.8mm (H)
Working Temperature	0~+70°C (commercial grade)
	-40~+85°C (industrial grade)
Debug UART	1x Debug serial port (UART2, TTL, 3-pin 2.54mm pitch pin headers)
Ethernet	1x 10/100/1000 Mbps Ethernet
USB	1x USB 2.0 OTG (Type-C)
	2x USB 2.0 Host (Type-A)
WiFi/Bluetooth	1x 2.4G/5G Dual-Band WiFi and Bluetooth 5.0 Module (AP6256)
Antenna	1x Antenna interface for WiFi/BT Module
Display	1x HDMI output interface (support 1080p@60fps resolution)
LED	1x LED (System indicator - Green)

Key Applications

Medical Equipment

Indutrial Gateway

Industrial Control

Industrial HMI

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYS-8MMQ6-V2-8E2D-180-C-B	MIMX8MM6DVTLZAA	4×Cortex-A53@1.8GHz+Cortex-M4@400MHz	2GB DDR4	8GB eMMC	0°C~+70°C	135mm x 74.5mm x 35.8mm	Linux Ubuntu
MYS-8MMQ6-V2-8E2D-160-I-B	MIMX8MM6CVTKZAA	4×Cortex-A53@1.6GHz+Cortex-M4@400MHz			-40°C~+85°C		

FZ5 EdgeBoard AI Box

- AMD/Xilinx Zynq UltraScale+ ZU5EV MPSoC based on 1.5 GHz Quad Arm Cortex-A53 and 600MHz Dual Cortex-R5 Cores
- 8GB DDR4 (64-bit, 2400MHz), 32GB eMMC, 64MB QSPI Flash, 32KB EEPROM
- 4x USB 3.0, Gigabit Ethernet, RS232, RS485, CAN, Micro-SD, Mini DP, HDMI-IN, Debug …
- Computing Power up to 2.4TOPS, Runs at 55 FPS for ResNet-50
- Supports 8- to 16-channel Video Decoding and 4- to 8-channel Intelligent Analysis
- Supports Running PetaLinux

FZ5 EdgeBoard AI Box Front-view

FZ5 EdgeBoard AI Box Back-view

Features	Description
CPU	Xilinx Zynq UltraScale+ XCZU5EV-2SFVC784I (784 Pin Package)MPSoC
RAM	8GB DDR4 (64-bit, 2400MHz)
Storage	32GB eMMC + 64MB QSPI Flash + 32KB EEPROM, 1x Micro SD card slot
Power Supply	DC 12V/3A
Dimensions	Body: 120mm x 100mm x 50mm, Hanger: 148mm x 100mm
Working Temperature	-40~+70°C
Working Humidity	20% ~ 90%, non-condensing
Serial Ports	1x USB-to-UART Port, 1x RS232, 1x RS485
Ethernet	1x 10/100/1000 Mbps Ethernet
USB	4x USB 3.0 Host
CAN	1x CAN Interface
Display	1x HDMI In port, 1x Mini DisplayPort 4K/30fps, 1x FPC_40PIN (MIPI-CSI)
User I/O	1x 1.27mm pitch 2 x 50-pin IO Expansion Interface (5 x PS_MIO, 69 x PL_IO)
Buttons	1x System Reset Button
LEDs	1x Red Power LED, 1x Green Status LED
RTC	1x 3V Rechargeable RTC Battery Interface (battery is not soldered by default, Model MS621T is recommended)
	1x 1.5V Non-Rechargeable RTC Battery Holder (battery is not provided by default, Model AG3 or LR41 is recommended)
Software	Supports PetaLinux

Key Applications

Intelligent Security | Medical Diagnosis | Artificial Intelligence (AI) | Consumer Electronics

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Other Storage	Software
MYS-ZU5EV-32E8D-EDGE-BOX	XCZU5EV-2SFVC784I	4x Cortex-A53@1.5GHz+ 2x Cortex-R5@600MHz	8GB DDR4	32GB eMMC	-40°C~+70°C	64MB QSPI Flash 32KB EEPROM	PetaLinux

ODM Services

Based on years of experience in the embedded industry, MYIR has amassed extensive product technology and project development expertise in embedded software and hardware development utilizing ARM/FPGA core processors. MYIR also offers professional and efficient customized services tailored to the specific requirements of customers.

Customized Solutions

SOM Customization

Base Board Customization

Whole Board Customization

Customized Service Process

1 Submit Requirements

2 Technical Evaluation

3 Business Communication

4 Sign Contract

5 Project Development

6 Prototype Delivery

7 Testing and Certification

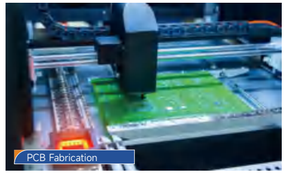
8 Customer Acceptance

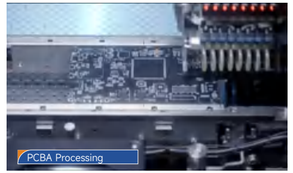
9 Mass Delivery

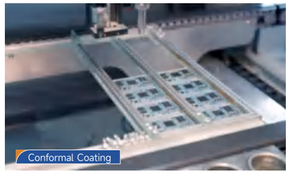
OEM Services

MYIR's Smart SMT factory is committed to providing customers with one-stop PCBA manufacturing services, encompassing PCB manufacturing, component procurement, SMT processing, assembly, and testing. Located in Longhua District, Shenzhen, the factory utilizes its advanced production equipment and management system, rigorous quality control procedures, comprehensive supply chain system, and robust engineering support to assist customers in enhancing production efficiency, reducing product delivery time, and ensuring production quality. It caters to a diverse range of customers across various industries, including industrial control, power communication, new energy, automotive electronics, medical electronics, smart home, security, and numerous other sectors globally.

One-stop PCBA Manufacturing Service







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